

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
15 September 2011 (15.09.2011)

(10) International Publication Number
WO 2011/112212 A1

(51) International Patent Classification:

A61F 13/15 (2006.01) B32B 3/10 (2006.01)
B26F 1/24 (2006.01) B32B 27/12 (2006.01)
B29C 65/00 (2006.01)

(21) International Application Number:

PCT/US2010/048415

(22) International Filing Date:

10 September 2010 (10.09.2010)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

12/721,905 11 March 2010 (11.03.2010) US

(71) Applicant (for all designated States except US): **THE PROCTER & GAMBLE COMPANY** [US/US]; One Procter & Gamble Plaza, Cincinnati, Ohio 45202 (US).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **STONE, Keith, Joseph** [US/US]; 1320 Carlin Court, Fairfield, Ohio 45014 (US). **YOUNG, Roger, Dale** [US/US]; 728 Bromley Road, Ft. Mitchell, Kentucky 41017 (US).

(74) Common Representative: **THE PROCTER & GAMBLE COMPANY**;

c/o Eileen L. Hughett, Global Patent Services, 299 East Sixth Street, Sycamore Building, 4th Floor, Cincinnati, Ohio 45202 (US).

(81) Designated States (unless otherwise indicated, for every kind of national protection available):

AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PE, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

[Continued on next page]

(54) Title: PROCESS FOR MAKING A FILM/NONWOVEN LAMINATE

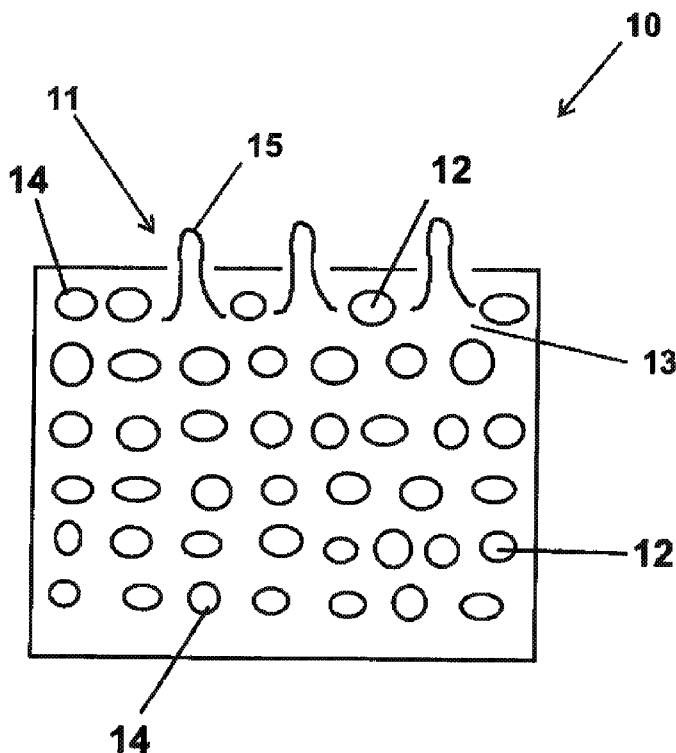


FIGURE 1

(57) Abstract: An article includes a film and a non-woven having fibers, and an embossed seal joining a portion of the film and the non-woven. The seal includes discrete extended elements formed in the film and surrounded by lands in the film. The discrete extended elements having open proximal ends, open or closed distal ends, and sidewalls disposed between the proximal and distal ends, and portions of the discrete extended elements having a thickness less than that of the lands. Fibers of the non-woven are embedded in at least one of the lands and in the sidewalls of the discrete extended elements through the open proximal ends.

WO 2011/112212 A1

(84) Designated States (*unless otherwise indicated, for every kind of regional protection available*): ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, SE, SI, SK,

SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— *with international search report (Art. 21(3))*

PROCESS FOR MAKING A FILM/NONWOVEN LAMINATE

FIELD OF THE INVENTION

The invention relates to a film/nonwoven article having an embossed seal and a process for forming the same.

BACKGROUND OF THE INVENTION

There are many known ways to temporarily adhere thin web materials together to form a seal, including, for example, the use of adhesives, the addition of mechanical fastening elements such as Velcro, and the melt-fusing of the webs by heat sealing or thermal-mechanical bonding. U.S. Patent No. 5,462,166, for example, discloses softening and fusing together thermoplastic polymeric films by the application of heat and pressure by a thermal-mechanical means. However, these methods add undesirable cost and inefficiency, as well complexity to the process for forming the seals. Additionally, seals formed in the melt state by fusing the webs together can undesirably tear at locations other than the seal and have stiff, plastic-like seals that are not appealing to users. Furthermore, these known sealing methods produce a seal that can exhibit a relatively loud noise when the two webs are separated and the seal is broken, for example, the characteristic loud sound of breaking of a Velcro seal.

Despite the knowledge in the art, there remains a desire to develop a more efficient process for making an article having a seal and for articles having a seal that is quiet when broke (i.e., when the two webs are separated at the seal). This is especially true for articles used as packaging for feminine care products. It is highly desirable to have sealed package that produces little to no noise when opening such packaging; allowing the user to more discretely open the packaging.

SUMMARY OF THE INVENTION

In one embodiment, an article includes a film and a non-woven having fibers, and an embossed seal joining a portion of the film and the non-woven. The seal includes discrete extended elements formed in the film and surrounded by lands in the film. The discrete extended elements having open proximal ends, open or closed distal ends, and sidewalls disposed between the proximal and distal ends, and portions of the discrete extended elements having a thickness less than that of the lands. Fibers of the non-woven are embedded in at least

one of the lands and in the sidewalls of the discrete extended elements through the open proximal ends.

In another embodiment, a process for forming an embossed seal includes feeding a film and a non-woven having fibers between a pressure source and a forming structure. The forming structure includes forming elements selected from the group consisting of discrete apertures, discrete depressions, discrete protruded elements, and combinations thereof. The process further includes applying pressure from the pressure source against the film, the non-woven, and the forming structure sufficient to conform the film to the forming elements of the forming structure and to embed at least a portion the fibers of the non-woven into the film to form an embossed seal comprising a plurality of discrete extended elements surrounded by lands. The discrete extended elements having open proximal ends and sidewalls, and the fibers of the non-woven being embedded in at least one of the lands and the sidewalls of the discrete extended elements through the open proximal ends of the discrete extended elements.

BRIEF DESCRIPTION OF THE DRAWINGS

While the specification concludes with claims particularly pointing out and distinctly claiming the subject matter that is regarded as the present invention, it is believed that the invention will be more fully understood from the following description taken in conjunction with the accompanying drawings. Some of the figures may have been simplified by the omission of selected elements for the purpose of more clearly showing other elements. Such omissions of elements in some figures are not necessarily indicative of the presence or absence of particular elements in any of the exemplary embodiments, except as may be explicitly delineated in the corresponding written description. None of the drawings are necessarily to scale.

Figure 1 is a top view of a forming structure in accordance with an embodiment of the disclosure;

Figure 2A is a perspective view of a forming structure in accordance with an embodiment of the disclosure illustrating the distinction between apertures and depressions;

Figure 2B is an enlarged perspective view of a portion of the forming structure having discrete protruded elements;

Figure 3A is a Scanning Electron Microscopy (SEM) image of an embossed seal in accordance with an embodiment of the disclosure;

Figure 3B is a magnified SEM image of the embossed seal of Figure 3A;

Figure 3C is a magnified SEM image of an embossed seal in accordance with an embodiment of the disclosure.

Figure 4 is a schematic representation of a process in accordance with an embodiment of the disclosure;

Figure 5A is a schematic representation of an embossed seal in accordance with an embodiment of the disclosure, illustrating the nonwoven being disposed on the side of the film having the open proximal ends of the discrete extended elements;

Figure 5B is a schematic representation of an embossed seal in accordance with an embodiment of the disclosure, illustrating the nonwoven being disposed on the side of the film having the distal ends of the discrete extended elements;

Figure 6 is a cross-sectional view of discrete extended elements of an embossed seal in accordance with an embodiment of the disclosure;

Figure 7 is a perspective view of discrete extended elements with open distal ends of an embossed seal in accordance with an embodiment of the disclosure;

Figure 8 is a schematic representation of a process in accordance with an embodiment of the disclosure, illustrating a static gas pressure plenum; and

Figure 9 is a schematic illustration of a continuous process for making an embossed web in accordance with an embodiment of the disclosure.

DETAILED DESCRIPTION OF THE INVENTION

Disclosed herein is an article having a seal adhering portions of at least a film and a nonwoven and a process for forming the article that overcomes one or more of the aforementioned shortcomings of the prior art. Specifically, embodiments of the article now make possible an article that is substantially quieter upon separation of the film and the nonwoven. Embodiments of the process now make possible a more efficient web sealing process. For example, embodiments of the article and the process can now make possible the ability to avoid the use of costly adhesives or additional mechanical adhering elements, such as hooks/loops (i.e. Velcro) and ridges/grooves, and complex processes associated with applying adhesives or the mechanical adhering elements. Embodiments of the article and process can

also make possible the ability to avoid the use of complex processes that melt and fuse the film and the nonwoven together to form the seal. Such seals can be very loud and/or lead to tearing of the film and nonwoven (rather than separation at the seal) upon separation.

With reference to Figures 3A, 3B, and 3C, in one embodiment, the article generally includes at least a film 33, a nonwoven 34, and an embossed seal 16 joining portions of the film 33 and the nonwoven 34. The seal includes discrete extended elements 22 surrounded by lands 13 formed in the film 33. The discrete extended elements 22 have open proximal ends 30, open or closed distal ends 24, and sidewalls disposed between the proximal and distal ends 24. The seal further includes fibers 23 of the nonwoven 34 embedded into at least one of the lands 13 and in the sidewalls of the discrete extended elements 22. The discrete extended elements 22 can be thinned relative to the lands 13. For example, distal ends 24 and/or sidewalls of the discrete extended elements 22 can be thinned. The embossed seal 16, which includes discrete extended elements 22 having fibers 23 of the nonwoven 34 embedded therein has high interfacial surface area between the film 33 and the nonwoven 34.

The discrete extended elements 22 extend in the z-direction to form three dimensional elements. The discrete extended elements 22 having the fibers 23 embedded therein or in the lands 13 surrounding the discrete extended elements 22 are believed to generate high shear strength, preventing separation of the film 33 and the nonwoven 34 during manipulation of the article. Surprisingly, even without adhesives, additional mechanical adhering elements, or melt fusing of the film 33 and the nonwoven 34, seals can also have very high peel strengths. Without intending to be bound by theory, it is believed that the strength of the embossed seal 16 is a function of the high interfacial surface area of the regions of the film 33 having fibers 23 of the nonwoven 34 embedded therein, the ability of the film 33 and the nonwoven 34 to adhere to themselves and to each other, and the ease with which the embossed seal 16 can be deformed.

The interfacial surface area of the film 33 and the nonwoven 34 is a function of at least the geometry of the discrete extended elements 22 and the density of the discrete extended elements 22 in the embossed seal 16. It is believed that the peel strength of the embossed seal 16 increases with increasing interfacial surface area. The ability of the film 33 and the nonwoven 34 to adhere to themselves and to each other is a function of at least the coefficient of friction the film 33 and the nonwoven 34, the surface energies of the film 33 and the nonwoven 34, and attractive forces such as van der Waals forces, dipole-dipole interactions, electrostatic forces, hydrogen bonds, and the like between the film 33 and the fibers 23 of the nonwoven 34

and/or between contacting portions of the film 33 with the film 33 and/or the fibers 23 of the nonwoven 34 with fibers 23 of the nonwoven 34. It is believed that the peel strength of the embossed seal 16 generally increases with an increasing ability of the film 33 and the nonwoven 34 to adhere to themselves and to each other.

It is also believed that the peel strength increases if the embossed seal 16 is more flexible, rather than rigid. With a more flexible embossed seal 16, the film 33 and the nonwoven 34 can move and flex together and, thus, remain in intimate contact in the sealed regions when being flexed. It is believed that more flexible seals result when lower modulus and/or lower gauge films and nonwovens are used. The film 33 and the nonwoven 34 may have a greater tendency to separate when flexed if the embossed seal 16 is rigid, and such separation could weaken the peel strength of the embossed seal 16.

Referring to Figure 4, the process of forming the embossed seal 16 generally includes feeding a film 33 and a nonwoven 34 having fibers 23 between a pressure source (e.g., a compliant substrate 44) and a forming structure 10 comprising a plurality of discrete forming elements 11. The forming elements 11 can include, for example, discrete protruded elements 15, discrete apertures 12, discrete depressions 14, or combinations thereof. The process further includes applying pressure from the pressure source against the film 33, the nonwoven 34, and the forming structure 10 sufficient to conform portions of the film 33 to the discrete forming elements 11 and to embed at least a portion of the fibers 23 of the nonwoven 34 into the film 33, thereby forming an embossed seal 16. The embossed seal 16 includes a plurality of discrete extended elements 22 surrounded by lands 13. The discrete extended elements 22 have open proximal ends 30 and sidewalls. Fibers 23 of the nonwoven 34 are embedded in at least one of the lands 13 and the sidewalls of the discrete extended elements 22 through the open proximal ends 30. These aspects of the article and the process are described in further detail below. In addition, in certain embodiments, the fibers 23 are contained by film 33, such as, for example, when the fibers 23 do not extend through film 33. In certain embodiments, discrete extended elements 23 have open distal ends 30, and the fibers 23 do not extend through the film 23 and out the open distal end 30. Furthermore, in certain embodiments, the fibers 23 do not form tufts with respect to film 23.

FORMING STRUCTURE

Referring to Figures 1 and 2, a forming structure 10 useful in the process of the present disclosure includes a plurality of discrete forming elements 11. The discrete forming elements

11 can include discrete protruded elements 15, discrete apertures 12, discrete depressions 14, or a combination thereof. The forming structure 10 can further include lands 13 completely surrounding the discrete forming elements 11. The discrete forming elements 11 of the forming structure 10 can be small in scale relative to typical patterns used on forming structures in conventional embossing processes. The process of the disclosure can produce embossed seals 16 that include relatively high aspect ratio extended elements 11 with thinned distal ends 24 and/or sidewalls, even without heating film and the nonwoven and even at high speeds. The forming structure 10 can include, for example, portions having discrete forming elements 11, and portions 19 not having discrete forming elements.

The forming structure 10 is sometimes referred to as a forming screen. Figure 2A illustrates the distinction between apertures 12 and depressions 14. As used herein, "apertures" refers to an opening in the forming structure 10 that does not include a bottom surface limiting the depth of the opening. In contrast, as used herein, "depressions" refers to an opening in the forming structure 10 having a bottom surface limiting the depth of the opening to be less than the thickness of the forming structure 10. The bottom surface can be, for example, porous or non-porous. For example, the bottom surface can include an opening, having a width smaller than the diameter of the depression 14 that vents the depression 14 by allowing air to pass through the depression 14. In one embodiment, the forming structure 10 has a means to allow any air trapped under the film 33 to escape. For example, a vacuum assist can be provided to remove the air under the film 33 so as not to increase the required compliant pressure. The bottom surface can be flat, rounded, or sharp. The forming structure 10 can be a solid roll, or have a thickness of about 25 microns to about 5000 microns, or about 100 microns to about 3000 microns. The apertures 12 and depressions 14 can have a depth of about 10 microns to about 500 microns, or about 25 microns to about 5000 microns. As used herein, the depth of the aperture 12 corresponds to the thickness of the forming structure 10 because the aperture 12 has no bottom surface limiting its depth. In one embodiment the apertures 12 and depressions 14 can have a depth substantially equal to the thickness of the film 33, at least twice the thickness of the film 33, or at least three times the thickness of the film 33. Preferably, the apertures 12 and depressions 14 have a depth that is at least three times the thickness of the film 33. In addition, in certain embodiments, such as, for example, as shown in Figure 3A, the discrete protruded elements 15 can be closely spaced, such that the space between the discrete protruded elements 15 can act as a depression during the web forming process.

The perimeter of the apertures 12 or depressions 14 on the film/nonwoven contacting surface of the forming structure 10 can have a straight edge or can have a radius of curvature as measured from the film/nonwoven contacting surface of the forming structure 10 into the aperture 12 or depression 14. The radius of curvature can be about 0 microns to about 2000 microns, preferably about 0 microns to about 25 microns, and more preferably about 2 microns to about 25 microns. In one embodiment, an angled taper, commonly known as a chamfer, is used. In one embodiment a combination of straight edges and radii are used.

The discrete protruded elements 15 can have a height of at least about 50 microns, at least about 75 microns, at least about 100 microns, at least about 150 microns, at least about 250 microns, or at least about 380 microns. The discrete protruded elements 15 can have a diameter, which for a generally cylindrical structure is the outside diameter. For non-uniform cross-sections, and/or non-cylindrical structures of protruded elements 15, diameter d_p is measured as the average cross-sectional dimension of protruded elements 15 at $\frac{1}{2}$ the height h_p of the protruded elements 15, as shown in Figure 2B. The discrete protruded elements 15 can have diameter d_p that can be from about 10 microns to about 5,000 microns, about 50 microns to about 5,000 microns, about 500 microns to about 5,000 microns, about 50 microns to about 3,000 microns, about 50 microns to about 500 microns, about 65 microns to about 300 microns, about 75 microns to about 200 microns, or about 800 microns to about 2,500 microns.

In one embodiment, the discrete protruded elements 15 of the forming structure 10 will have a diameter of less than about 500 microns.

For each protruded element 15, a protruded element aspect ratio, defined as h_p/d_p , can be determined. Protruded elements 15 can have an aspect ratio h_p/d_p of at least about 0.5, at least about 0.75, at least about 1, at least about 1.5, at least about 2, at least about 2.5, or at least about 3 or higher. In general, because the actual height h_p of each individual protruded element 15 may vary, an average height (" $h_{p_{avg}}$ ") of a plurality of protruded elements 15 can be determined by determining a protruded element average minimum amplitude (" $A_{p_{min}}$ ") and a protruded element average maximum amplitude (" $A_{p_{max}}$ ") over a predetermined area of forming structure 10. Likewise, for varying cross-sectional dimensions, an average protrusion diameter (" $d_{p_{avg}}$ ") can be determined for a plurality of protrusions 15. Such amplitude and other dimensional measurements can be made by any method known in the art, such as by computer aided scanning microscopy and related data processing. Therefore, an average aspect ratio of the

protruded elements 15, (“ $AR_{p_{avg}}$ ”) for a predetermined portion of the forming structure 10 can be expressed as hp_{avg}/dp_{avg} .

The discrete protruded elements 15 of the forming structure 10 can have distal ends 24 that are flat, rounded or sharp, depending upon whether it is desired to produce an embossed seal 16 having discrete extended elements 22 with distal ends 24 that are open (requiring a sharper protruded element on the forming structure 10) or closed (requiring a more rounded protruded element on the forming structure 10). The rounded distal ends 24 of the discrete protruded elements 15 of the forming structure 10 can have a certain tip radius, such as from about 5 microns to about 150 microns, from about 10 microns to about 100 microns, from about 20 to about 75 microns, or from about 30 microns to about 60 microns.

The sidewalls of the discrete protruded elements 15 can be completely vertical or can be tapered. In one embodiment, the discrete protruded elements 15 have tapered sidewalls, as tapered sidewalls can have an impact on durability and longevity of the pressure source. For example, when using a compliant substrate 44, the tapered sidewalls can ease the compression or tension on compliant substrate 44 as it conforms around discrete forming elements 11 of the forming structure 10. This can also allow the film 33 and the nonwoven 34 to more easily separate from the forming structure 10 after embossing. In one embodiment, the sidewalls will typically have a degree of taper of from about 0° to about 50°, from about 2° to about 30°, or from about 5° to about 25°.

In one embodiment, the forming elements can have varying geometries, such as height of the protruded elements 15 and depth of the apertures 12 or depressions 14, which can selectively impact the bond strength of certain regions of the film 33 and the nonwoven 34. For example, the forming elements can gradually increase in height or over a range of tens or hundreds of adjacent protruded elements 15, which can result in the film 33 having discrete extended elements 22 with varying heights, which in turn can result in an embossed seal 16 having a strength gradient. Other features of the forming structure 10 which results in corresponding features of the discrete extended elements 22 can be adjusted to form an embossed seal 16 having a strength gradient. For example, the forming structure 10 can include an area density gradient of forming elements.

In one embodiment, the protruded elements 15 can be spherical, ellipsoid, or snowman-shaped, having different or varying diameters along the height of the protruded element.

The apertures 12 or depressions 14 have a diameter, which for a generally cylindrical structure is the inside diameter. For non-uniform cross-sections, and/or non-cylindrical structures of apertures 12 or depressions 14, diameter is measured as the average cross-sectional dimension of apertures 12 or depressions 14 at the top surface of the forming structure 10. Each aperture 12 or depression 14 can have diameter of about 40 microns to about 2,000 microns. Other suitable diameters include, for example, about 50 microns to about 500 microns, about 65 microns to about 300 microns, about 75 microns to about 200 microns, about 10 microns to about 5000 microns, about 50 microns to about 5000 microns, about 500 microns to about 5000 microns, or about 800 microns to about 2,500 microns.

In one embodiment, the diameter of apertures 12 or depressions 14 is constant or decreases with increasing depth. In another embodiment, the diameter of the apertures 12 or depressions 14 increases with increasing depth. For example, the discrete apertures 12 or depressions 14 can have a first diameter at a first depth and a second diameter at a second depth deeper than the first depth. For example, the first diameter can be larger than the second diameter. For example, the second diameter can be larger than the first diameter.

The sidewalls of the discrete apertures 12 or depressions 14 can be completely vertical or can be tapered. In one embodiment, the discrete apertures 12 or depressions 14 have tapered sidewalls. This can allow the film 33 and the nonwoven 34 to more easily separate from the forming structure 10 after embossing. In one embodiment, the sidewalls will typically have a degree of taper of about 0° to about -50° to about 50°, about -30° to about 30°, about 0° to about 50°, about 2° to about 30°, or about 5° to about 25°.

The discrete forming elements 11 of the forming structure 10 can have a variety of different cross-sectional shapes, such as generally columnar or non-columnar shapes, including circular, oval, hour-glass shaped, star shaped, polygonal, and the like, and combinations thereof. Polygonal cross-sectional shapes include, but are not limited to, rectangular, triangular, hexagonal, or trapezoidal. In one embodiment, the discrete depressions 14 can have a length substantially equal to the length of the forming structure 10 so as to form grooves about substantially the entire length of the forming structure 10. In another embodiment, the discrete protruded elements 15 can have a length substantially equal to the length of the forming structure 10 so as to form an extended protruded element about substantially the entire length of the forming structure 10. For example, when the forming structure 10 is in the form of a roll, the grooves and/or extended protruded elements 15 can be formed about the entire

circumference of the roll. The grooves and/or extended protruded elements 15 can be substantially straight (e.g., consistently parallel to the edge of the roll) or can be wavy. Alternatively, in certain embodiments, the forming structure 10 does not include discrete forming elements 11 provided only in machine directional rows. For example, in certain embodiments, the forming structure 10 includes discrete forming elements 11 provided in cross-directional rows.

In general, the forming structure 10, for a given portion of thereof, will include at least about 0.015 discrete forming elements 11 per square centimeter, such as, for example, at least about 4 discrete forming elements 11 per square centimeter, at least about 10 discrete forming elements 11 per square centimeter, at least about 95 discrete forming elements 11 per square centimeter, at least about 240 discrete forming elements 11 per square centimeter, about 350 to about 10,000 discrete forming elements 11 per square centimeter, about 500 to about 5,000 discrete forming elements 11 per square centimeter, or about 700 to about 3,000 discrete forming elements 11 per square centimeter.

The discrete forming elements 11 can have an average edge-to-edge spacing between two adjacent apertures 12 or depressions 14 of about 30 microns to about 1000 microns, about 50 microns to about 800 microns, about 150 microns to about 600 microns, or about 180 microns to about 500 microns.

In certain embodiments, a portion (or area) of the forming structure 10 can include area densities of discrete forming elements 11 as described in the preceding paragraph, while other portions (or areas) of the forming structure 10 may include no discrete forming elements 11. The areas of the forming structure 10 having no discrete forming elements 11 can be located in a different horizontal plane. In other embodiments, the discrete forming elements 11 of the forming structure 10 can be located in different horizontal planes of the forming structure 10. The regions having no discrete forming elements 11 and/or the regions having discrete forming elements 11 located in different horizontal planes of the forming structure 10 can be in the form of a specific pattern or design, such as a flower, bird, ribbon, wave, cartoon character, logo, and the like, so that the embossed seal 16 will have a region that stands out visually from, and/or has a different hand feel when touched relative to, the remainder of the film 33 and nonwoven 34. For example, the embossed seal 16 can include a non-embossed region that stands out visually from, and/or has a different hand feel from embossed regions. U.S. Patent No. 5,158,819 provides suitable examples of forming structures for use in these embodiments.

In one embodiment, a ratio of the average depth of the apertures 12 or depressions 14 or the average height of the discrete protruded elements 15 to the thickness of the film 33 is at least about 1:1, at least about 2:1, at least about 3:1, at least about 4:1, at least about 5:1, or at least about 10:1. This ratio can be important to ensure the film 33 is sufficiently stretched so that each becomes permanently deformed to create an embossed seal 16, especially at desirable process conditions and speed.

Forming structure 10 can be made of any material or materials that can be formed to have discrete forming elements 11 having the necessary dimensions to make an embossed seal 16 and is dimensionally stable over process temperature and pressure ranges experienced by forming structure 10.

In one embodiment, discrete forming elements 11 are made integrally with forming structure 10. That is, the forming structure 10 is made as an integrated structure, either by removing material or by building up material. For example, the forming structure 10 having the required relatively small scale discrete forming elements 11 can be made by local, selective removal of material, such as by chemical etching, mechanical etching, or by ablating by use of high-energy sources such as electrical-discharge machines (EDM) or lasers, or by electron beam (e-beam), or by electrochemical machining (ECM). In one embodiment, the forming structure 10 may be constructed by a photo etched laminate process generally in accordance with the teachings of U.S. Patent No. 4,342,314.

In one method of making a suitable forming structure 10, a base material susceptible to laser modification is laser "etched" to selectively remove material to form apertures 12 or depressions 14. By "susceptible to laser modification", it is meant that the material can be selectively removed by laser light in a controlled manner, recognizing that the wavelength of light used in the laser process, as well as the power level, may need to be matched to the material (or vice-versa) for optimum results. Laser etching can be achieved by known laser techniques, selecting wavelength, power, and time parameters as necessary to produce the desired protruded element dimensions. Currently known materials susceptible to laser modification include thermoplastics such as polypropylene, acetal resins such as DELRIN® from DuPont, Wilmington DE, USA, thermosets such as crosslinked polyesters, or epoxies, or even metals such as aluminum, copper, brass, nickel, stainless steel, or alloys thereof. Optionally, thermoplastic and thermoset materials can be filled with particulate or fiber fillers to increase compatibility with lasers of certain wavelengths of light and/or to improve modulus or

toughness to make more durable apertures 12 or depressions 14. For example, certain polymers, such as PEEK, can be laser machined to higher resolution and at higher speeds by uniformly filling the polymer with sufficient amounts of hollow carbon nanotube fibers.

In one embodiment, a forming structure 10 can be laser machined in a continuous process. For example, a polymeric material such as DELRIN® can be provided in a cylindrical form as a base material having a central longitudinal axis, an outer surface, and an inner surface, the outer surface and inner surface defining a thickness of the base material. It can also be provided as a solid roll. A moveable laser source can be directed generally orthogonal to the outer surface. The moveable laser source can be moveable in a direction parallel to the central longitudinal axis of the base material. The cylindrical base material can be rotated about the central longitudinal axis while the laser source machines, or etches, the outer surface of the base material to remove selected portions of the base material in a pattern that defines a plurality of discrete apertures 12 or depressions 14 and/or discrete protruded elements 15.

The forming structure 10 can be in the form of a flat plate, a roll, a belt, an endless belt, a sleeve, or the like. In one preferred embodiment, the forming structure 10 is in the form of a roll. In another preferred embodiment, the forming structure 10 is in the form of an endless belt. Endless belts can be formed in accordance with the teachings of U.S. Patent Nos. 7,655,176, 6,010,598, 5,334,289, and 4,529,480.

The forming structure can be utilized in a low strain rate process, such as that described in U.S. Application No. 2008/0224351 A1, to produce an embossed web of the present invention wherein the activation belt is a solid or compliant substrate 44.

If the forming structure 10 includes protruded elements 15 and discrete apertures 12 and depressions 14, the discrete extended elements 22 can be formed in the film 33 extending from the surface of the film 33 opposite the surface from which the discrete extended elements 22 formed by the apertures 12 or depressions 14 of the forming structure 10 are formed. As a result, a two-sided embossed seal 16 can be created, having different patterns or dimensions of extended elements 22 on each side of the embossed seal 16. Depending upon the pressure generated between the forming structure 10 and compliant substrate 44, as well as the geometric shapes of the apertures 12 or depressions 14 and optional pillars or ridges of the forming structure 10, the discrete extended elements 22 of the embossed seal 16 can have closed or open distal ends 24.

PRESSURE SOURCE

The pressure source utilized to provide a force against the forming structure 10 can be, for example, a compliant substrate 44, a static pressure plenum 36, a velocity pressure source, or combinations thereof. One example of a device suitable for providing velocity air pressure to conform the film 33 and the nonwoven 34 to the forming structure is a high pressure air knife. High pressure air knives are commercially available from, for example, Canadian Air Systems. Another example of a suitable device and process utilizing air pressure to conform the film 33 and the nonwoven 34 to the forming structure 10 is described in U.S. Patent No. 5,972,280. An example of a device suitable for providing water pressure to conform the film 33 and the nonwoven 34 to the forming structure 10 is a water plenum, such as that described in U.S. Patent No. 7,364,687. For example, a suitable process for making the embossed seal 16 is a hydroforming process. Non-limiting examples of hydroforming processes are described in U.S. Patent No. 4,609,518 and U.S. Patent No. 4,846,821. A forming structure 10, a film 33, and a nonwoven 34 as described herein can be utilized in such hydroforming processes.

Another suitable process, for example, for making the embossed seal 16 is a vacuum forming process. Non-limiting examples of vacuum forming processes are described in U.S. Patent Nos. 4,456,570 and 4,151,240, and U.S. Application Publication No. 2004/0119207 A1. A forming structure 10, a film 33, and a nonwoven 34 as described herein can be utilized in such vacuum forming processes to produce the embossed seal 16 of the present disclosure. Other suitable processes are described in U.S. Patent No. 4,846,821 and U.S. Application Publication No. 2004/0119207 A1.

Compliant Substrate

Referring to Figure 9, at a minimum, the outer surface of the compliant substrate 44 (i.e., the surface of the compliant substrate 44 oriented towards the forming structure 10) includes a compliant material 46. For example, the compliant substrate 44 can include a rigid material 48 covered by a compliant material 46. The rigid material 48 can be a metal (such as steel), a plastic, or any other material that is significantly harder than the compliant material 46. The thickness of the compliant material 46 covering the rigid material 48 will typically be no greater than about 26 mm, and preferably about 1 mm to about 26 mm, more preferably about 1 mm to about 7 mm. Alternatively, the entire compliant substrate 44 can be made of a compliant material 46.

The compliant substrate 44 or compliant material 46 can include elastomers, felts, liquid-filled bladders, gas-filled bladders, and combinations thereof. In one embodiment, the

compliant substrate 44 is a porous elastomer. The compliant substrate 44, or the compliant material 46 utilized in the compliant substrate 44, preferably has resilient properties (such as compression recovery) such that the compliant material 46 rebounds fast enough to facilitate the process, especially a continuous process.

The compliant substrate 44, or the compliant material 46 utilized in the compliant substrate 44, preferably also has enough durability to emboss large quantities of film 33 and nonwoven 34 material. As a result, the compliant substrate 44 preferably has a suitable degree of toughness and abrasion resistance, wherein the compliant substrate 44 will tend to be abraded by the forming structure 10 during the process.

The compliant substrate 44 can be in the form of a flat plate, a roll, a belt, an endless belt, a sleeve, or the like. In one embodiment, the compliant substrate 44 is a metal roll covered with a compliant material 46, such as an elastomer. In another embodiment, the compliant substrate 44 and the forming structure 10 are both in the form of rolls. In another embodiment, the compliant substrate 44 is a roll that has a diameter greater than the diameter of the forming structure 10 roll. In another embodiment, the compliant substrate 44 is a roll that has a diameter less than the diameter of the forming structure 10 roll. In another embodiment, the compliant substrate 44 roll has a diameter that is the same as the diameter of the forming structure 10 roll.

The compliant substrate 44, or the compliant material 46 utilized in the compliant substrate 44, will typically have a hardness of about 30 to about 90 durometer, preferably about 35 to about 80 durometer, and more preferably about 40 to about 70 durometer, on the Shore A scale. Hardness on the Shore A scale is typically determined by using an ASTM D2240 durometer, such as the Model 306 Type A Classic Style Durometer available from PTC Instruments of Los Angeles, California. It should be recognized that the compliant substrate 44 can exhibit varying hardness, for example lower hardness near the outer surface and higher hardness towards the inner surface of the compliant substrate 44 (i.e. varying hardness in the z-direction of the compliant substrate 44) or varying hardness across the outer surface of the compliant substrate 44 (i.e. varying hardness in the x-y plane of the compliant substrate 44).

The compliant material 46 utilized in the compliant substrate 44 will typically have a tensile modulus of about 1 to about 20 MPa, preferably about 2 to about 18 MPa, and more preferably about 3 to about 10 MPa. The tensile modulus of the compliant material 46 can be determined at a strain rate of 0.1 sec^{-1} .

Non-limiting examples of suitable compliant materials include natural rubber, urethane rubber, polyurethane rubber, chlorosulfonated polyethylene rubber (available under the tradename HYPALON[®] from DuPont), chloroprene rubber, norbornene rubber, nitrile rubber, hydrogenated nitrile rubber, styrene rubber, styrene-butadiene rubber, butadiene rubber, silicone rubber, ethylene-propylene-diene ("EPDM") rubber, isobutylene-isoprene rubber, felt (such as pressed wool felt), and the like. Particularly useful compliant materials are isoprene, EPDM, neoprene, and HYPALON[®] having a Shore A hardness of about 40 to about 70 durometer.

The compliant material 46 can also be a material, such as an absorbent core, that can be fed between a rigid material 48 and the forming structure 10 along with the film 33 and the nonwoven 34. Such a material can serve to generate pressure against the film 33 and the nonwoven 34 and forming structure 10 so as to emboss the film 33 and the nonwoven 34. Such a material can then be later incorporated, along with the embossed seal 16, into a finished consumer product, such as a feminine hygiene product.

The compliant substrate 44 can optionally include recessed regions of a depth sufficient to prevent the embossing of the film 33 and the nonwoven 34 in the particular region, or only minimally emboss the film 33 and the nonwoven 34 in the particular region.

Static Pressure Plenum

Referring to Figure 8, a static pressure plenum 36 is utilized to provide a force against the film 33 and the nonwoven 34 to conform the film 33 to the discrete forming elements 11 of the forming structure 10 and embed fibers 23 of the nonwoven 34 into the film 33. Preferably, the static pressure plenum 36 is a static gas pressure plenum. The gas can be air, nitrogen, carbon dioxide, and combinations thereof.

The static pressure plenum 36 exerts a pressure on the film 33 and the nonwoven 34. The static gas pressure plenum 36 can include a hood 38, which defines a plenum 40 adjacent the film 33 and the nonwoven 34. The hood 38 can include at least one high pressure gas inlet 42 allowing high pressure gas or other fluid to enter the hood 38 creating the static pressure conditions. Under static gas pressure conditions, there is no velocity and density impinging upon the unembossed film 33 and the nonwoven 34 as with a velocity pressure source such as an air knife. Rather, a static high gas pressure is maintained in the hood 38 which creates a pressure differential across the film 33 and the nonwoven 34, between the static pressure plenum 36 facing surface of the film 33 and the nonwoven 34 and the forming structure 10 facing surface of the film 33 and the nonwoven 34. The pressure differential is sufficient to conform the film 33

to the discrete forming elements 11 of the forming structure 10. The pressure differential can be enhanced, for example, by applying a vacuum on the forming structure 10 facing surface of the film 33.

FILM AND NONWOVEN

A film 33 and a nonwoven 34 are joined by an embossed seal 16. Suitable films include materials that can be deformed by the pressure source, such that the film conforms to the discrete elements 11 of the forming structure 10 to produce discrete extended elements 22 in the film 33. Preferably, the film 33 has the ability to adhere to itself and/or other film and/or nonwoven materials.

The film 33 typically includes synthetic material, metallic material, biological material (in particular, animal-derived materials), or combinations thereof. The film 33 and the nonwoven 34 can be the same material or can be different materials. The film 33 and the nonwoven 34 can optionally include cellulosic material. In one embodiment, the film 33 and the nonwoven 34 are free of cellulosic material. Non-limiting examples of suitable films, such as polymeric or thermoplastic films, collagen films, chitosan films, rayon, cellophane, and the like. Suitable films further include laminates or blends of these materials.

The film 33 can be any materials, such as a polymeric film, having sufficient material properties to be formed into an embossed seal 16 described herein by the embossing process of the disclosure. The film 33 will typically have a yield point and the film 33 is preferably stretched beyond its yield point to form the discrete extended elements 22 of the embossed seal 16. That is, the film 33 should have sufficient yield properties such that the film 33 can be strained without rupture to an extent to produce the desired discrete extended elements 22 with closed distal ends 24 or, in the case of an embossed seal comprising discrete extended elements 22 having open distal ends 24, rupture to form open distal ends 24. As disclosed below, process conditions such as temperature can be varied for a given polymer to permit it to stretch with or without rupture to form the embossed seal 16 having the desired discrete extended elements 22. In general, therefore, it has been found that preferred starting materials to be used as the film 33 exhibit low yield and high-elongation characteristics. In addition, as discussed previously, the film 33 is preferably strain hardened. Examples of films include films comprising low density polyethylene (LDPE), linear low-density polyethylene (LLDPE), polypropylene, and blends thereof. Other suitable polymeric films include thermoplastic films such as polyethylene, polypropylene, polystyrene, polyethylene terephthalate (PET), polymethylmethacrylate

(PMMA), polyvinyl alcohol (PVA), nylon, polytetrafluoroethylene (PTFE) (e.g., TEFLON), or combinations thereof. Suitable polymeric films can include blends or mixtures of polymers.

In certain embodiments, the film 33 can comprise a sustainable polymer, such as polylactides, polyglycolides, polyhydroxyalkanoates, polysaccharides, polycaprolactones, and the like, or mixtures thereof.

The thickness of each of the film 33 prior to embossing will typically range from about 5 to about 300 microns, about 5 microns to about 150 microns, about 5 microns to about 100 microns, or about 15 microns to about 50 microns. Other suitable thicknesses includes about 1, 2, 3, 4, 5, 6, 7, 8, 9, 10, 20, 30, 40, 50, 60, 70, 80, 90, 100, 150, 200, 250, or 300 microns.

One material found suitable for use as the film 33 is DOWLEX 2045A polyethylene resin, available from The Dow Chemical Company, Midland, MI, USA. A film 33 of this material having a thickness of 20 microns can have a tensile yield of at least 12 MPa; an ultimate tensile of at least 53 MPa; an ultimate elongation of at least 635%; and a tensile modulus (2% Secant) of at least 210 MPa (each of the above measures determined according to ASTM D 882). Other suitable films include polyethylene film that is about 25 microns (1.0 mil) thick and has a basis weight of about 24 grams per square meter ("gsm") available from available from RKW US, Inc. (Rome, Georgia) and polyethylene/polypropylene film having a basis weight of about 14 gsm and a thickness of about 15 microns available from RKW US, Inc.

The nonwoven 34 includes fibers 23. The nonwoven 34 can have a high density such that it behaves similar to a film 33 material. One example of such a high density nonwoven 34 is TYVEK®. The nonwoven 34 can comprise unbonded fibers, entangled fibers, tow fibers, or the like. fibers 23 can be extensible and/or elastic, and may be pre-stretched for processing. fibers 23 of nonwoven 34 can be continuous, such as those produced by spunbonded methods, or cut to length, such as those typically utilized in a carded process. fibers 23 can be absorbent, and can include fibrous absorbent gelling materials. fibers 23 can be bicomponent, multiconstituent, shaped, crimped, or in any other formulation or configuration known in the art for nonwovens and fibers 23.

The nonwoven 34 can be any known nonwoven including nonwovens comprising polymer fibers having sufficient elongation properties to be formed into an embossed seal 16. In general, the polymeric fibers can be bondable, either by chemical bond (e.g. by latex or adhesive bonding), pressure bonding, or thermal bonding. The nonwoven 34 can comprise about 100% by weight thermoplastic fibers. The nonwoven 34 can comprise as little as about 10% by weight

thermoplastic fibers. Likewise, the nonwoven 34 can comprise any amount by weight thermoplastic fibers in 1% increments between about 10% and about 100%.

The total basis weight of nonwoven 34 (including laminate or multi-layer nonwovens) can range from about 8 gsm to about 500 gsm, such as, for example, from about 8 gsm to about 50 gsm, depending on the ultimate use of the article, and can be produced in 1 gsm increments between about 8 and about 500 gsm. The constituent fibers 23 of the nonwoven 34 can be polymer fibers, and can be monocomponent, bicomponent and/or biconstituent fibers, hollow fibers, non-round fibers (e.g., shaped (e.g., trilobal) fibers or capillary channel fibers), and can have major cross-sectional dimensions (e.g., diameter for round fibers, long axis for elliptical shaped fibers, longest straight line dimension for irregular shapes) ranging from about 0.1 to about 500 microns in 0.1 micron increments, such as, for example, from about 5 to about 50 microns.

The nonwoven 34 may be formed by known nonwoven 34 extrusion processes, such as, for example, known meltblowing processes or known spunbonding processes.

The nonwoven 34 may be extensible, elastic, or nonelastic. The nonwoven 34 may be a spunbonded web, a meltblown web, or a bonded carded web. If the nonwoven 34 is a web of meltblown fibers, it may include meltblown microfibers. The nonwoven 34 may be made of fiber forming polymers such as, for example, polyolefins. Polyolefins include one or more of polypropylene, polyethylene, ethylene copolymers, propylene copolymers, and butene copolymers.

Films and nonwovens, such as polymeric films and nonwovens, will typically have a glass transition temperature of about -100°C to about 120°C, or about -80°C to about 100°C, or other suitable ranges. Films and nonwovens, such as polymeric films and nonwovens, can have a melting point of about 100°C to about 350°C. For example, a film 33 and/or a nonwoven 34 formed of LDPE or a blend of LDPE and LLDPE has a melting point of about 110°C to about 122°. A film 33 and/or a nonwoven 34 formed of polypropylene has a melting point of about 165°C. A film 33 and/or a nonwoven 34 formed of polyester has a melting point of about 255°C. A film 33 and/or a nonwoven 34 formed of Nylon 6 has a melting point of about 215°C. A film 33 and/or a nonwoven 34 formed of PTFE has a melting point of about 327°C.

In one embodiment, the process is carried out at a temperature less than the lower of the melting point of the film 33 and the melting point of the nonwoven 34. For example, the process can be carried out at 10°C less than the lower of melting point of the film 33 and the

melting point the nonwoven 34. In another embodiment, the process is carried out at a temperature substantially equal to the lower of the melting point of the film 33 and the melting point of the nonwoven 34. In one embodiment, the process is carried out at a temperature greater than the glass transition temperature of the film 33 and/or the nonwoven 34. Regardless of the temperature used in the process, the process conditions on the whole are selected so as to not melt-fuse the film 33 and the nonwoven 34. For example, higher temperatures may be coupled with short dwell times such that none of the film 33 or the nonwoven 34 materials melt to cause fusion of the film 33 and the nonwoven 34.

Optionally, the film 33 and/or the nonwoven 34 may be plasticized to decrease the elastic moduli and/or make them less brittle prior to embossing in the process.

In one embodiment, the film 33 and/or the nonwoven 34 are strain hardened. The strain hardened properties of the film 33 can be desirable to facilitate conformation of the film 33 to the discrete forming elements 11 of the forming structure 10. This can be preferred for producing embossed seals 16 wherein closed distal ends 24 of the extended elements 22 of the embossed seal 16 are desired.

The film 33 and the nonwoven 34 should also be sufficiently deformable and have sufficient ductility for use in forming the embossed seal 16. The term "deformable" as used herein describes a material which, when stretched beyond its elastic limit, will substantially retain its newly formed conformation, as well as exhibit thinning. For example, the film 33 can exhibit thinning at or near the distal ends 24 of the discrete extended elements 22 of the resulting embossed seal 16.

The film 33 can be a laminate of two or more film 33 layers, and can be a co-extruded laminate. For example, the film 33 can include two layers. In another example, the film 33 can include three layers, wherein the innermost layer is referred to as a core layer, and the two outermost layers are referred to as skin layers. In one embodiment, the film 33 includes a three layer coextruded laminate having an overall thickness of about 25 microns (0.001 in.), with the core layer having a thickness of about 18 microns (0.0007 in.); and each skin layer having a thickness of about 3.5 microns (0.00015 in.). In one embodiment, the layers can include polymers having different stress-strain and/or elastic properties.

The film 33 can be made using conventional procedures for producing multilayer films on conventional coextruded film-making equipment. Where layers comprising blends are required, pellets of the above described components can be first dry blended and then melt

mixed in the extruder feeding that layer. Alternatively, if insufficient mixing occurs in the extruder, the pellets can be first dry blended and then melt mixed in a pre-compounding extruder followed by repelletization prior to film extrusion. Suitable methods for making the film 33 are disclosed in U.S. Patent No. 5,520,875 and U.S. Patent No. 6,228,462.

In general, the ability to form high area density (or low average center-to-center spacing) discrete extended elements 22 on the embossed seal 16 can be limited by the thickness of film 33 and/or the nonwoven 34.

In certain embodiments, the film 33 and/or the nonwoven 34 can optionally further include a surfactant. If utilized, preferred surfactants include those from non-ionic families such as: alcohol ethoxylates, alkylphenol ethoxylates, carboxylic acid esters, glycerol esters, polyoxyethylene esters of fatty acids, polyoxyethylene esters of aliphatic carboxylic acids related to abietic acid, anhydrosorbitol esters, ethoxylated anhydrosorbitol esters, ethoxylated natural fats, oils, and waxes, glycol esters of fatty acids, carboxylic amides, diethanolamine condensates, and polyalkyleneoxide block copolymers. Molecular weights of surfactants selected can range from about 200 grams per mole to about 10,000 grams per mole. Preferred surfactants have a molecular weight of about 300 to about 1,000 grams per mole.

If utilized, the surfactant level initially blended into the film 33 and/or the nonwoven 34 can be as much as 10 percent by weight of the total web. Surfactants in the preferred molecular weight range (300-1,000 grams/mole) can be added at lower levels, generally at or below about 5 weight percent of the total web.

In various embodiments, the film 33 and/or the nonwoven 34 can also include additives to enhance a web's ability to adhere to itself and other webs. Any known additives for increasing a film's 33 or nonwoven 34's adhesive ability can be used. For example, low molecular weight polymers, for example, polyisobutene (PIB) and poly(ethylene-vinylacetate) (EVA) copolymer can be added to the web materials. When used with LDPE, for example, PIB and EVA have chains readily interact with each other and their lower molecular weight makes them more mobile within the host polymer matrix.

Preferably, the film 33 and the nonwoven 34 are free of release agents and/or low surface energy chemical functional groups on the surface of the webs. It has been found that the presence of low surface energy chemical functional groups on the surface of the webs can reduce the bond strength of the webs. For example, silicone adhesive release agents typically applied to one or more of the web surfaces to be bonded can render a resulting bond weak,

especially as compared to a bond formed in the same material without the topically applied silicone adhesive release agent. It is believed that the attractive forces between the surfaces are reduced by low surface energy treatments. Other low surface energy surface treatments include fluorocarbons.

In certain embodiments, the film 33 and/or the nonwoven 34 can also include titanium dioxide in the polymer blend. Titanium dioxide can provide for greater opacity of the embossed seal 16. Titanium dioxide can be added at up to about 10 percent by weight of the web, such as low density polyethylene.

Other additives, such as particulate material, e.g., carbon black, iron oxide, mica, calcium carbonate (CaCO_3), particulate skin treatments or protectants, or odor-absorbing actives, e.g., zeolites, can optionally be added in the film 33 and/or the nonwoven 34. In some embodiments, embossed seals 16 comprising particulate matter, when used in skin-contacting applications, can permit actives to contact the skin in a very direct and efficient manner. Specifically, in some embodiments, formation of discrete extended elements 22 can expose particulate matter at or near the distal ends 24 thereof. Therefore, actives such as skin care agents can be localized at or near distal ends 24 of the discrete extended elements 22 to permit direct skin contact with such skin care agents when the embossed seal 16 is used in skin contacting applications.

The average particle size of the particulate material, if utilized in the film 33 and/or the nonwoven 34, will typically be 0.1 microns to about 200 microns, 0.2 microns to about 200 microns, or about 5 microns to about 100 microns. The use of certain particulate materials, such as mica interference particles, can dramatically improve the visual appearance of the embossed seal 16.

The film 33 and/or the nonwoven 34 can also optionally include colorants, such as pigment, lake, toner, dye, ink or other agent used to impart a color to a material, to improve the visual appearance of the embossed seal 16.

Suitable pigments herein include inorganic pigments, pearlescent pigments, interference pigments, and the like. Non-limiting examples of suitable pigments include talc, mica, magnesium carbonate, calcium carbonate, magnesium silicate, aluminum magnesium silicate, silica, titanium dioxide, zinc oxide, red iron oxide, yellow iron oxide, black iron oxide, carbon black, ultramarine, polyethylene powder, methacrylate powder, polystyrene powder, silk powder, crystalline cellulose, starch, titanated mica, iron oxide titanated mica, bismuth oxychloride, and the like.

Suitable colored films and nonwovens are described in co-pending U.S. Application Serial No. 12/721,947, filed March 11, 2010, and U.S. Application Serial No. 12/721,965, filed March 11, 2010.

The film 33 and/or the nonwoven 34 can also optionally include fillers, plasticizers, and the like.

EMBOSSSED SEAL

The article having the embossed seal 16 can have various desired structural features and properties such as desired soft hand feel and an aesthetically pleasing visual appearance. The embossed seal 16 includes discrete extended elements 22 surrounded by lands 13. The discrete extended elements 22 have open proximal ends 30 and sidewalls. Fibers 23 of the nonwoven 34 are embedded in at least one of the lands 13 and the sidewalls of the discrete extended elements 22. Referring to Figure 5B, in one embodiment, the nonwoven 34 is disposed on the side of the film 33 containing the distal ends 24 of the discrete extended elements 22, and fibers 23 of the nonwoven 34 are embedded in the lands 13 surrounding the discrete extended elements 22. Referring to Figure 5Aa, in another embodiment, the nonwoven 34 is disposed on the side of the film 33 containing the open proximal ends 30 of the discrete extended elements 22, and fibers 23 of the nonwoven 34 are embedded in the sidewalls of the discrete extended elements 22 through the open proximal ends 30 and/or the lands 13 surrounding the discrete extended elements 22.

In one embodiment, a portion of the discrete extended elements 22 are thinned relative to the lands 13 surrounding the discrete extended elements 22. For example, the distal ends 24 and/or the sidewalls of the discrete extended elements 22 can be thinned relative to the lands 13. The discrete extended elements 22 having the fibers 23 of the nonwoven 34 embedded therein and/or in the lands 13 surrounding the discrete extended elements 22 have high interfacial surface area. In addition, as disclosed above, it is believed that there is sufficient friction and/or attractive forces to retain the film 33 and the nonwoven 34 joined at the embossed seal 16. Separation of the film 33 and the nonwoven 34 at the embossed seal 16 requires sufficient force to separate the fibers 23 embedded in the lands 13 and/or the discrete extended elements 22 from the discrete extended elements 22 and the lands 13. Such separation generates little to no noise as compared to prior art bonding methods, such as those involving fusing of the film 33 and the nonwoven 34 by heat and pressure. When the at least two layers of the article are separated at the embossed seal 16, the noise generated by the separation is noticeably less than the noise generated by a conventional seal formed by a thermo-mechanical bonding process, such as

described in U.S. Patent No. 5,462,166. For example, when the at least two layers of the article are separated at the embossed seal 16, the sound pressure level generated from the separation can be less than about 70 dB, less than about 65 dB, or less than about 60 dB. The embossed seal 16 is substantially quieter upon separation than a seal formed by a conventional thermo-mechanical bonding process using conventional processing conditions, such as, for example, those described in U.S. Patent No. 5,462,166. For example, the embossed seal 16 can generate a sound pressure level upon separation that is at least about 2 dB less, at least about 3 dB, at least about 4 dB less, at least about 5 dB, at least about 6 dB less, at least about 7 dB, at least about 8 dB less, at least about 9 dB, or at least about 10 dB less than the sound pressure level generated from a seal formed by conventional thermo-mechanical bonding process having substantially the same peel strength as the embossed seal 16 and separated under the same conditions as the embossed seal 16. Substantially the same peel strength refers to a peel strength within at least about 50%, at least about 60%, at least about 70%, or at least about 80% of the peel strength of the embossed seal 16.

The embossed seal 16 can have a peel strength at least substantially equal to a conventional seal, such as a conventional thermo-mechanical seal, as measured by the Peel Strength Test. For example, the embossed seal 16 can have a peel strength that is at least within 30%, 40%, 50%, 60%, 70%, 80%, 90%, or 100% of the peel strength of a conventional, thermo-mechanical seal.

The Peel Strength Test can be performed according to the method disclosed in U.S. Patent No. 5,462,166.

The film 33 and the nonwoven 34 are positioned between the forming structure 10 and the pressure source, and a pressure is applied to conform the film 33 to the discrete forming elements 11 of the forming structure 10. Referring to Figures 3A, 3B, and 3C, an article with an embossed seal 16 having discrete extended elements 22 with fibers 23 of the nonwoven 34 embedded in the sidewalls of the discrete extended elements 22 and/or the lands 13 surrounding the discrete extended elements 22 is thereby produced. In addition to being embedded in the discrete extended elements 22 and/or the lands 13, bundles of fibers 23 of the nonwoven 34 can also be squeezed together between adjacent discrete extended elements 22. As shown in Figures 3A, 3B, 3C and 6, the discrete extended elements 22 have open proximal ends 30 and open (as shown in Figure 7) and or closed (as shown in Figures 3C and 4) distal ends 24.

Each of the film 33 and the nonwoven 34 can be a single layer of material or a multilayer coextruded or laminate material as described hereinbefore. Laminate film materials may be coextruded, as is known in the art for making laminate films, including films comprising skin layers.

The discrete extended elements 22 are formed as protruded extensions of the film 33, generally on a first surface 26 thereof. In certain embodiments, the film 33 is pushed through nonwoven 34, such as, for example, as shown by apertures 21 in Figure 3A and by discrete extended elements 22 in Figure 3C. Surprisingly, the film 33 can be pushed through nonwoven 34 when the nonwoven is on the outer surface of the extended element. Without being bound by theory, it is believed that the film extended elements can interlock with the fiber interstices of the nonwoven, creating additional seal strength.

The number, size, and distribution of discrete extended elements 22 on the embossed seal 16 can be predetermined based on desired bond strength, soft feel, and visual effects. It is believed that the high interfacial surface area in intimate contact between the fibers 23 of the nonwoven 34 and the discrete extended elements 22 increases as the height, diameter, aspect ratio, and/or the number of discrete extended elements 22 per unit area increases. It is further believed that an increase in interfacial surface area results in a corresponding increase in bond strength of the embossed seal 16.

Referring to Figure 6, the discrete extended elements 22 can be described as protruding from a first surface 26 of the film 33. As such, the discrete extended elements 22 can be described as being integral with the film 33, and formed by permanent local plastic deformation of the film 33. The discrete extended elements 22 can be described as having a side wall(s) 28 defining an open proximal portion and a closed or open distal end 24. The discrete extended elements 22 each have a height h measured from a minimum amplitude A_{\min} between adjacent extended elements 22 to a maximum amplitude A_{\max} at the closed or open distal end 24. The discrete extended elements 22 have a diameter d , which for a generally cylindrical structure is the outside diameter at a lateral cross-section. By "lateral" is meant generally parallel to the plane of the first surface 26. For generally columnar discrete extended elements 22 having non-uniform lateral cross-sections, and/or non-cylindrical structures of discrete extended elements 22, diameter d is measured as the average lateral cross-sectional dimension at $\frac{1}{2}$ the height h of the discrete extended element. Thus, for each discrete extended element, an aspect ratio, defined as h/d , can be determined. The discrete extended element can have an aspect ratio h/d of at least

about 0.2, at least about 0.3, at least about 0.5, at least about 0.75, at least about 1, at least about 1.5, at least about 2, at least about 2.5, or at least about 3. The discrete extended elements 22 will typically have a height h of at least about 30 microns, at least about 50 microns, at least about 65, at least about 80 microns, at least about 100 microns, at least about 120 microns, at least about 150 microns, or at least about 200 microns. The extended elements 22 will typically be at least the same height as the thickness of the film 33, or at least 2 times the thickness of the film 33, or preferably at least 3 times the thickness of the film 33. The discrete extended elements 22 will typically have a diameter d of about 50 microns to about 5,000 microns, about 50 microns to about 3,000 microns, about 50 microns to about 500 microns, about 65 microns to about 300 microns, or about 75 microns to about 200 microns. For discrete extended elements 22 that have generally non-columnar or irregular shapes, a diameter of the discrete extended element can be defined as two times the radius of gyration of the discrete extended element at $\frac{1}{2}$ height.

For discrete extended elements 22 that have shapes, such as ridges, that extend lengthwise across the entire film 33 material such that the extended elements 22 have a portion of the sidewalls of the extended elements 22 that are open, a diameter of a discrete extended element can be defined as the average minimal width between two opposing sidewalls of the extended element at $\frac{1}{2}$ height.

In general, because the actual height h of any individual discrete extended element can be difficult to determine, and because the actual height may vary, an average height h_{avg} of a plurality of discrete extended elements 22 can be determined by determining an average minimum amplitude A_{min} and an average maximum amplitude A_{max} over a predetermined area of the embossed seal 16. Such average height $h_{p_{avg}}$ will typically fall within the ranges of heights described above. Likewise, for varying cross-sectional dimensions, an average diameter d_{avg} can be determined for a plurality of discrete extended elements 22. Such average diameter d_{avg} will typically fall within the ranges of diameters described above. Such amplitude and other dimensional measurements can be made by any method known in the art, such as by computer aided scanning microscopy and data processing. Therefore, an average aspect ratio AR_{avg} of the discrete extended elements 22 for a predetermined portion of the embossed seal 16 can be expressed as h_{avg}/d_{avg} .

In one embodiment, the diameter of a discrete extended element is constant or decreases with increasing amplitude (amplitude increases to a maximum at closed or open distal end 24). The diameter, or average lateral cross-sectional dimension, of the discrete extended elements 22

can be a maximum at proximal portion and the lateral cross-sectional dimension steadily decreases to distal end. This structure 10 is believed to be desirable to help ensure the embossed seal 16 can be readily removed from the forming structure 10. In another embodiment, the diameter of the discrete extended elements 22 increases with increasing amplitude. For example, the discrete extended elements 22 can have a mushroom shape.

Thinning of the film 33 can occur due to the relatively deep drawing required to form high aspect ratio discrete extended elements 22. For example, thinning can be observed at or near the closed or open distal ends 24 and/or along the sidewalls of the discrete extended elements 22. By "observed" is meant that the thinning is distinct when viewed in magnified cross-section. Such thinning can be beneficial as the thinned portions offer little resistance to compression or shear when touched. For example, when a person touches the embossed seal 16 on the side exhibiting discrete extended elements 22, the fingertips of the person first contact the closed or open distal ends 24 of the discrete extended elements 22. Due to the high aspect ratio of the discrete extended elements 22, and the wall thinning of the film 33 at or near the distal ends 24 and/or the sidewalls, the discrete extended elements 22 offer little resistance to the compression or shear imposed on the embossed seal 16 by the person's fingers. This lack of resistance is registered as a feeling of softness, much like the feeling of a velour fabric.

Thinning of the film 33 at or near the closed or open distal ends 24 and/or sidewalls can be measured relative to the thickness of the film 33 prior to embossing or relative to the thickness of the land area that completely surrounds the discrete extended elements 22 of the embossed seal 16. The film 33 will typically exhibit thinning of at least about 25%, at least about 50%, or at least about 75% relative to the thickness of the film 33. The film 33 will typically exhibit thinning of at least about 25%, at least about 50%, or at least about 75% relative to the thickness of the land area surrounding the discrete extended elements 22 of the embossed seal 16.

It should be noted that a fluid impermeable article having only the discrete extended elements 22 as disclosed herein, and not having macroscopic apertures 12 or discrete extended elements 22 having open distal ends 24, can offer softness for any application in which fluid permeability is not required. Thus, in one embodiment, the article includes an embossed seal 16 exhibiting a soft and silky tactile impression on at least one surface thereof, the silky feeling surface of the embossed seal 16 exhibiting a pattern of discrete extended elements 22 having fibers 23 of a nonwoven 34 embedded in the sidewalls of the discrete extended elements 22

and/or in the lands 13 surrounding the discrete extended elements 22, each of the discrete extended elements 22 being a protruded extension of the film 33 surface and having sidewalls defining an open proximal portion and a closed or open distal end 24. In certain embodiments, the discrete extended elements 22 have a maximum lateral cross-sectional dimension at or near the open proximal portion.

The “area density” of the discrete extended elements 22, which is the number of discrete extended elements 22 per unit area of first surface 26, can be optimized and the embossed seal 16 will typically include about 4 to about 10,000, about 10 to about 10,000, about 95 to about 10,000, about 240 to about 10,000, about 350 to about 10,000, about 500 to about 5,000, or about 700 to about 3,000 discrete extended elements 22 per square centimeter. In general, the center-to-center spacing can be optimized for adequate tactile impression, while at the same time minimizing entrapment of materials, such as fluids, between discrete extended elements 22. The center-to-center spacing between adjacent discrete extended elements 22 can be about 100 microns to about 5,000 microns, about 100 microns to about 1,000 microns, about 30 microns to about 800 microns, about 150 microns to about 600 microns, or about 180 microns to about 500 microns.

In one embodiment, the article can include an unsealed portion 17 disposed adjacent to the embossed seal 16, the unsealed portion 17 comprising portions of the film 33 and the nonwoven 34 in which the nonwoven 34 is not embedded in the lands 13 or in the sidewalls of the discrete extended elements 22 through the open proximal ends 30 of the discrete extended elements 22. For example, the unsealed portion 17 can be devoid of discrete extended elements 22, as illustrated in Figure 4. In another embodiment, the embossed seal 16 is disposed along opposing sides of the film 33 and the nonwoven 34, and the unsealed portion 17 is disposed between the opposing sides having the embossed seal 16.

PROCESS FOR MAKING EMBOSSED SEAL

Referring to Figure 4, the process for forming an embossed seal 16 includes feeding the film 33 and the nonwoven 34 between the pressure source, for example a compliant substrate 44 as illustrated in Figure 4, and the forming structure 10 and applying a pressure from the pressure source against the film 33, the nonwoven 34, and the forming structure 10 sufficient to conform portions of the film 33 to the discrete forming elements 11 of the forming structure 10 to thereby form an embossed seal 16 having discrete extended elements 22 surrounded by lands 13, with fibers 23 of the nonwoven 34 being embedded in the sidewalls of the discrete extended elements

22 and/or in the lands 13. The conformation of the film 33 to the forming structure 10 can be partial conformation, substantial conformation, or complete conformation, depending upon the pressure generated and the topography of the forming structure 10. While not being bound by theory, it is believed that open distal ends 24 can be formed by locally rupturing the film 33 while conforming the film 33 to the discrete forming elements 11 of the forming structure 10.

To obtain permanent deformation of the film 33 and the nonwoven 34 to form the embossed seal 16, the applied pressure is generally sufficient to stretch the film 33 beyond its yield point. The fibers of nonwoven 34 can also be compressed and/or stretched beyond their yield points.

The process can be a batch process or a continuous process. A batch process can involve providing individual sheets of the film 33 and the nonwoven placed between the forming structure 10 and pressure source.

A continuous process can involve providing rolls of the film 33 and the nonwoven 34 that are unwound and fed between the forming structure 10 and pressure source. The film 33 and the nonwoven 34 can also be provided on a single roll. The forming structure 10 can be, for example, in the form of a roll. As the film 33 and the nonwoven 34 pass between the forming structure 10 roll and the pressure source, an embossed seal 16 is formed. If the pressure source is a compliant substrate 44, the compliant substrate 44 can also be in the form of a roll.

The process can have relatively short dwell times. As used herein, the term "dwell time" refers to the amount of time pressure is applied to a given portion of the film 33 and the nonwoven 34, usually the amount of time a given portion of the film 33 and the nonwoven 34 spend positioned between the forming structure 10 and pressure source. The pressure is typically applied to the film 33 and the nonwoven 34 for a dwell time of less than about 5 seconds, less than about 1 second, less than about 0.5 second, less than about 0.1 second, less than about 0.01 second, or less than about 0.005 second. For example, the dwell time can be about 0.5 milliseconds to about 50 milliseconds. Even with such relatively short dwell times, embossed seals 16 can be produced with desirable structural features described herein. As a result, the process of the disclosure enables high speed production of embossed seals 16.

The film 33 and the nonwoven 34 can be fed between the forming structure 10 and the pressure source at a rate of at least about 0.01 meters per second, at least about 1 meter per second, at least about 5 meters per second, or at least about 10 meters per second. Other suitable

rates include, for example, at least about 0.01, 0.05, 0.1, 0.5, 1, 2, 3, 4, 5, 6, 7, 8, 9, or 10 meters per second.

Depending upon factors such as the shape of the discrete extended elements 22 on the forming structure 10 and the pressure applied, the distal ends 24 of the extended elements 22 of the embossed seal 16 produced can be either closed or open. In certain embodiments, a layer configuration wherein the nonwoven is on the outer surface of the extended element can also increase the formation of open distal ends, especially using lower basis weight nonwovens 34, such as, for example, nonwovens 34 having a basis weight of about 20 gsm or less, such as, for example, a basis weight of about 15 gsm or less, or about 10 gsm or less.

The process can be carried out at ambient temperature, meaning that no heat is intentionally applied to the forming structure 10, the pressure source, the film 33 or the nonwoven 34. It should be recognized, however, that heat can be generated due to the pressure between the forming structure 10 and the pressure source, especially in a continuous process. As a result, the forming structure 10 and/or the pressure source may be cooled in order to maintain the process conditions at the desired temperature, such as ambient temperature.

The process can also be carried out with the film 33 and/or the nonwoven 34 having an elevated temperature. For example, the temperature of the film 33 and/or the nonwoven 34 can be less than the lower of the melting point of the film 33 and the melting point of the nonwoven 34. For example, the temperature of the film 33 and/or the nonwoven 34 can be at least about 10°C below the lower of the melting point of the film 33 and the melting point of the nonwoven 34. The film 33 and/or the nonwoven 34, can have a temperature during the process of about 10°C to about 200°C, about 10°C to about 120°C, about 20°C to about 110°C, about 10°C to about 80°C, or about 10°C to about 40°C. The film 33 and/or the nonwoven 34 can be heated using a heated pressure source, for example a heated fluid pressure source for a static pressure plenum 36 or a heated compliant substrate 44, and/or by heating the forming structure 10. For example, a heated gas can be used as the pressure source for the static pressure plenum 36.

In one embodiment, the neither the film 33 nor the nonwoven 34 is heated before being provided between the forming structure 10 and the compliant substrate 44. In another embodiment, none of the film 33, the nonwoven 34, the forming structure 10, and the compliant substrate 44 are heated before providing the film 33 and the nonwoven 34 between the forming structure 10 and the compliant substrate 44.

In general, the process of the present disclosure can be carried out at a temperature of from about 10°C to about 200°C, from about 10°C to about 120°C, from about 10°C to about 80°C, or from about 10°C to about 40°C. The temperature can be measured by, for example, a non-contact thermometer, such as an infrared thermometer or a laser thermometer, measuring the temperature at the nip between the pressure source and forming structure 10. The temperature can also be determined using temperature sensitive material such as Thermolabel available from Paper Thermometer Company.

An average pressure is provided by the pressure source. The average pressure is sufficient to force the film 33 and the nonwoven 34, which is positioned between the forming structure 10 and pressure source, to conform the film 33 to the discrete forming elements 11 of the forming structure 10 and embed fibers 23 of the nonwoven 34 into the film 33 at the discrete extended elements 22 or surrounding lands 13, thereby forming an embossed seal 16. In general, the average pressure provided between the forming structure 10 and static pressure plenum 36 or by a velocity pressure source is about 0.1 MPa to about 25 MPa, about 0.5 MPa to about 20 MPa, about 0.7 MPa to about 10 MPa, about 1 MPa to about 7 MPa, about 1 MPa to about 20 MPa, about 0.5 MPa to about 10 MPa, about 10 MPa to about 25 MPa, or about 0.5 MPa to about 5 MPa. In general, the average pressure provided between the forming structure 10 and a compliant substrate 44 is about 1 MPa to about 100 MPa, about 5 MPa to about 70 MPa, about 10 MPa to about 60 MPa, or about 20 MPa to about 40 MPa. For example, the applied pressure can be up to about 30 MPa.

When a compliant substrate 44 is used as the pressure source, the forming structure 10 and compliant substrate 44 are impressed to a desired compression distance by applying a force to the forming structure 10 and/or compliant substrate 44. The “compression distance” is determined by measuring the distance the forming structure 10 is pressed into the compliant substrate 44. This distance can be measured by bringing the forming structure 10 and compliant substrate 44 into initial contact and then forcing the forming structure 10 and compliant substrate 44 together. The distance that the forming structure 10 and compliant substrate 44 are moved relative to each other subsequent to the initial contact is referred to as the “compression distance.” If the forming structure 10 and compliant substrate 44 are both rolls, the compression distance can be measured as the change in distance between the rotational axis of the forming structure 10 and the rotational axis of the compliant substrate 44 due to the force applied after initial contact.

The compression distance of the forming structure 10 and the compliant substrate 44 will typically be from about 0.1 mm to about 5 mm, from about 0.2 mm to about 4 mm, or from about 0.3 mm to about 3 mm.

The process can optionally be combined with other processes to further manipulate the article having the embossed seal 16. In one embodiment, such additional processes can be combined with the process on the same process manufacturing line to produce, for example, packaging for absorbent articles.

The process can further include applying pressure from a second pressure source. The second pressure source can be the same or different than the first pressure source and can be selected from the group consisting of a static liquid pressure plenum, a static gas pressure plenum, a velocity gas pressure source, such as an air knife, a velocity liquid pressure source, such as is used in conventional hydroforming process, and a compliant substrate 44. The pressures exerted on the film 33 and the nonwoven 34 by the second pressure source will typically be similar to those pressures exerted on the film 33 and the nonwoven by the first pressure source described hereinbefore. For example, the process can include using multiple static pressure plenums. In one embodiment, at least two static pressure plenums are provided and pressure is applied on a first portion of the film 33 and the nonwoven 34 between the forming structure 10 and a first static pressure plenum. Pressure can then be applied on the first portion of the film 33 and the nonwoven 34 between the forming structure 10 and a second static pressure plenum to further conform the first portion of the film 33 and the nonwoven 34 to the same protruded elements 15, apertures 12, or depressions 14 of the same forming structure 10. This can allow for enhancement of the discrete extended elements 22 formed by the process.

In one embodiment, the forming structure 10 includes a plurality of discrete depressions 14 and a plurality of discrete protruded elements 15. Referring to Figure 3A, the resulting embossed seal 16 can include a plurality of discrete extended elements 22 formed in the film 33 as well as a plurality of discrete apertures 21 formed in the film 33 and extending in an opposite direction as the discrete extended elements 22.

In another embodiment, the forming structure 10 includes a plurality of discrete apertures 12 and a plurality of discrete protruded elements 15. The resulting embossed seal 16 can include a plurality of discrete extended elements 22 formed in the film 33 and extending from the film 33 in opposite directions, wherein the discrete extended elements 22 formed by the apertures 12

extend in one direction while the discrete extended elements 22 formed by the discrete protruded elements 15 extending the opposite direction.

USES OF ARTICLES

The articles can be utilized in a number of different ways, including as packaging materials of absorbent articles, packaging (such as flow wrap, shrink wrap, or polybags), trash bags, food wrap, dental floss, wipes, electronic components, wall paper, clothing, aprons, window coverings, placemats, book covers, and the like.

The dimensions and values disclosed herein are not to be understood as being strictly limited to the exact numerical values recited. Instead, unless otherwise specified, each such dimension is intended to mean both the recited value and a functionally equivalent range surrounding that value. For example, a dimension disclosed as “40 mm” is intended to mean “about 40 mm.”

All documents cited in the Detailed Description of the Invention are, in relevant part, incorporated herein by reference; the citation of any document is not to be construed as an admission that it is prior art with respect to the present invention. To the extent that any meaning or definition of a term in this document conflicts with any meaning or definition of the same term in a document incorporated by reference, the meaning or definition assigned to that term in this document shall govern.

While particular embodiments of the present invention have been illustrated and described, it would be obvious to those skilled in the art that various other changes and modifications can be made without departing from the spirit and scope of the invention. It is therefore intended to cover in the appended claims all such changes and modifications that are within the scope of this invention.

CLAIMS

What is claimed is:

1. An article comprising:
a film and a non-woven comprising fibers; and
an embossed seal joining a portion of the film and the non-woven, the seal comprising discrete extended elements formed in the film and surrounded by lands in the film, the discrete extended elements having open proximal ends, open or closed distal ends, and sidewalls disposed between the proximal and distal ends, and portions of the discrete extended elements having a thickness less than that of the lands, wherein the fibers of the non-woven are embedded in at least one of the lands and in the sidewalls of the discrete extended elements through the open proximal ends.
2. The article of claim 1, wherein the non-woven is disposed on a side of the film containing the open proximal ends of the discrete extended elements.
3. The article of claim 1, wherein the non-woven is disposed on a side of the film containing the closed distal ends of the discrete extended elements.
4. The article of claim 1, wherein the embossed seal is free of adhesives.
5. The article of claim 1, wherein at least one of the distal ends and sidewalls of the discrete extended elements are thinned by at least about 25% relative to the lands.
6. The article of claim 1, wherein the film has a thickness of about 5 microns to about 150 microns.
7. The article of claim 1, wherein the non-woven has a basis weight of about 8 gsm to about 50 gsm.
8. The article of claim 1, wherein the fibers of the non-woven have a diameter of about 0.1 microns to about 50 microns.

9. The article of claim 1, wherein the discrete extended elements have a height at least substantially equal to a thickness of the film.
10. A process comprising:
 - feeding a film and a non-woven having fibers between a pressure source and a forming structure comprising forming elements selected from the group consisting of discrete apertures, discrete depressions, discrete protruded elements, and combinations thereof; and,
 - applying pressure from the pressure source against the film, the non-woven, and the forming structure sufficient to conform the film to the forming elements of the forming structure and to embed at least a portion of the fibers of the non-woven into the film to form an embossed seal comprising a plurality of discrete extended elements surrounded by lands, the discrete extended elements having open proximal ends and sidewalls, and the fibers of the non-woven being embedded in at least one of the lands and the sidewalls of the discrete extended elements through the open proximal ends of the discrete extended elements.
11. The process of claim 10, wherein the pressure source is selected from the group consisting of a static pressure plenum, a compliant substrate, a velocity pressure source, and combinations thereof.
12. The process of claim 10, wherein the pressure source is a compliant substrate.
13. The process of claim 12, wherein the applied pressure is about 1 MPa to about 100 MPa.
14. The process of claim 10, wherein the pressure source is a static pressure plenum.
15. The process of claim 14, wherein the applied pressure is about 0.1 MPa to about 25 MPa.
16. The process of claim 10, comprising applying pressure for a dwell time of about 0.5 milliseconds to about 50 milliseconds.

17. The process of claim 10, wherein the temperature of the film and the non-woven during the process is less than the lower of the melting point of the film and the melting point of the non-woven.
18. The process of claim 10, wherein the forming elements have an average diameter of about 10 microns to about 5000 microns
19. The process of claim 10, wherein the embossed seal is free from adhesive.
20. The process of claim 10, wherein the embossed seal is formed without melt-fusing the film and the nonwoven.

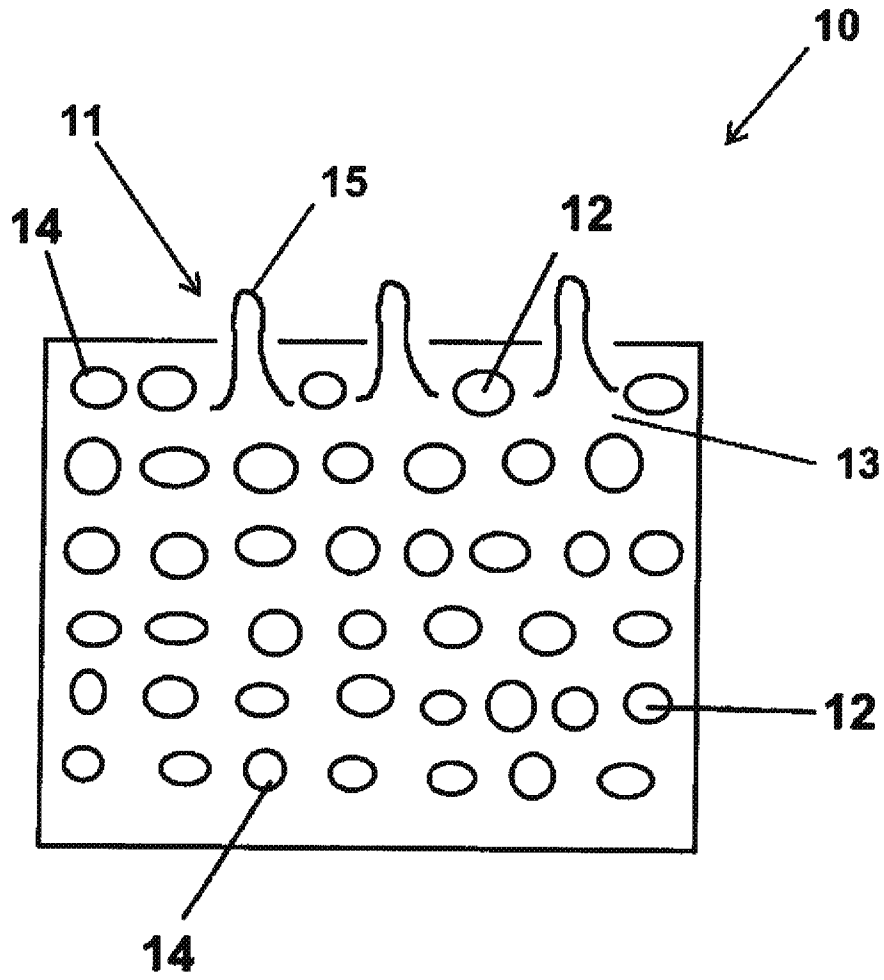


FIGURE 1

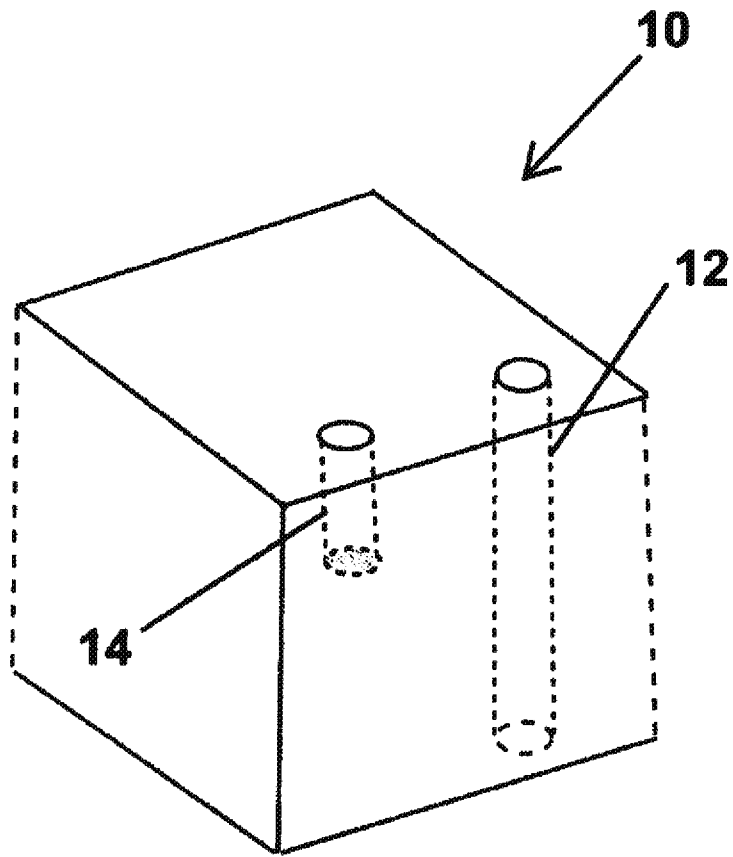


FIGURE 2A

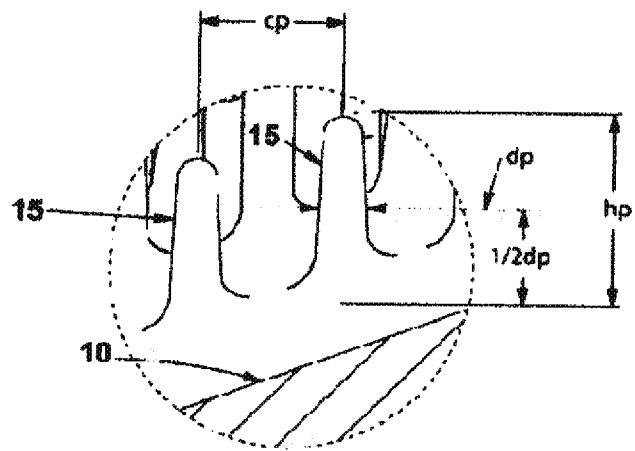


FIGURE 2B

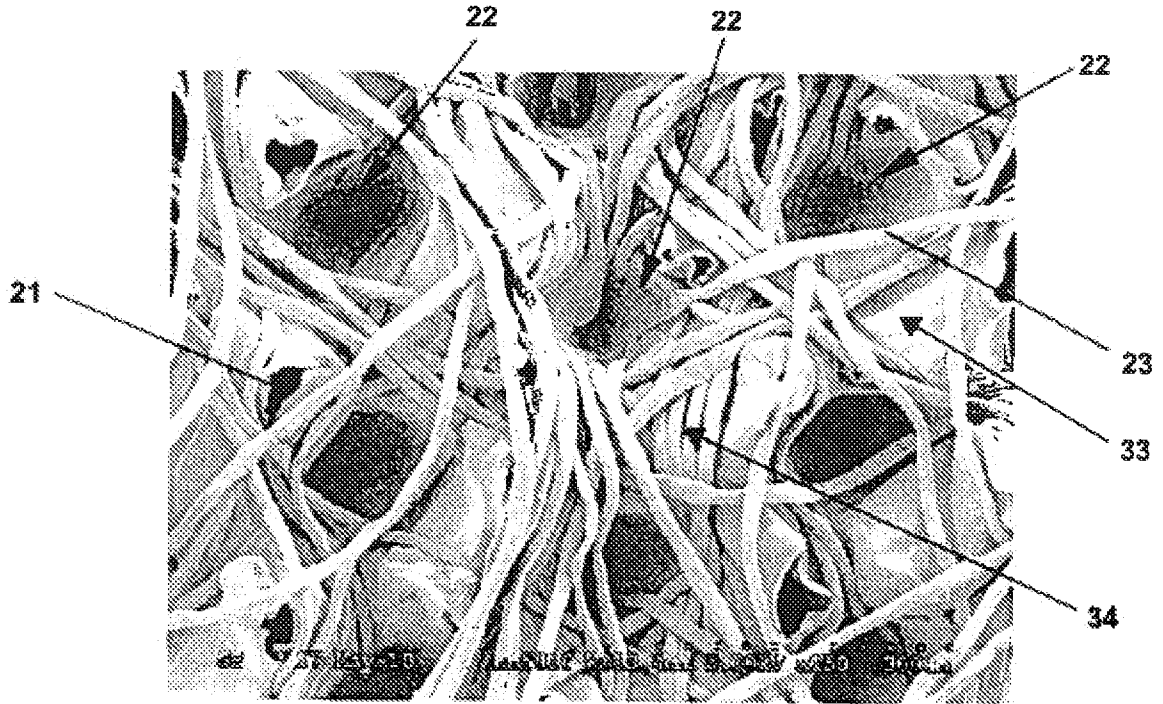


FIGURE 3A

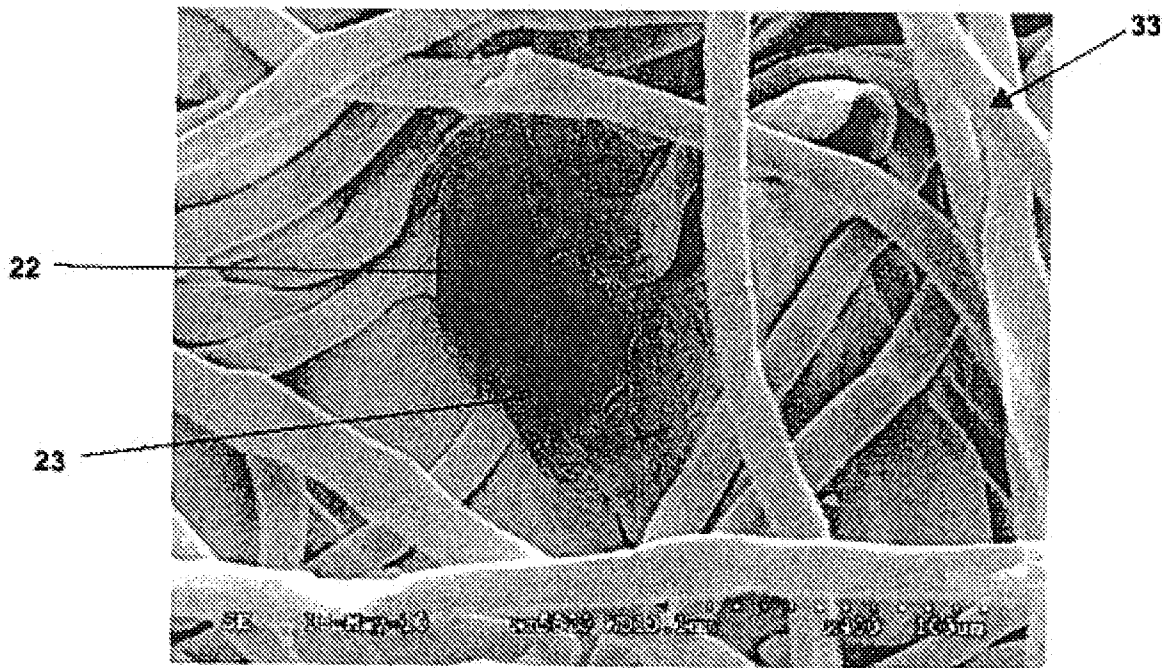


FIGURE 3B

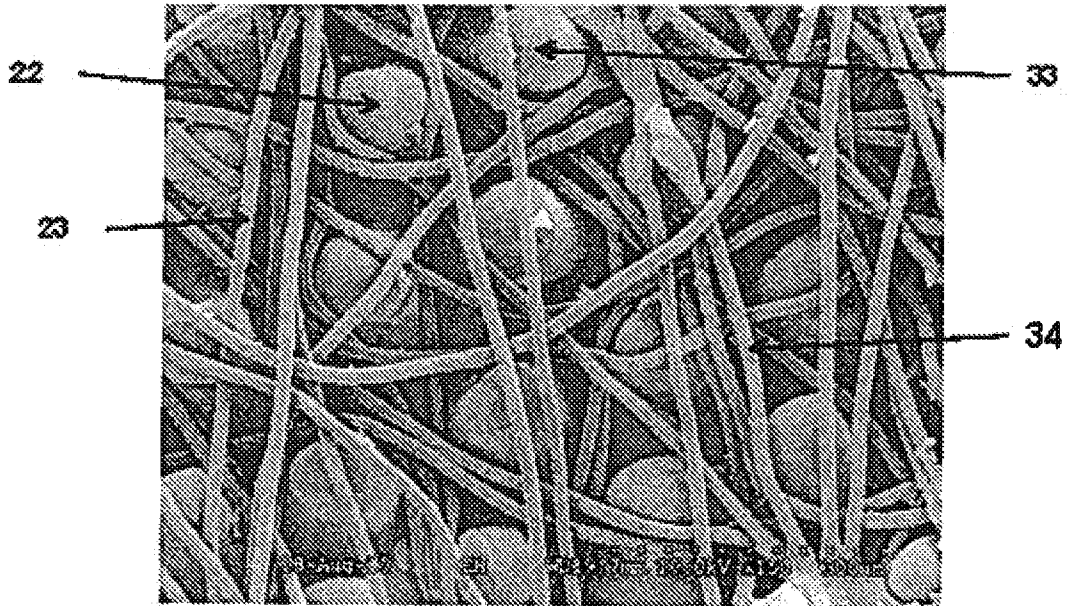


FIGURE 3C

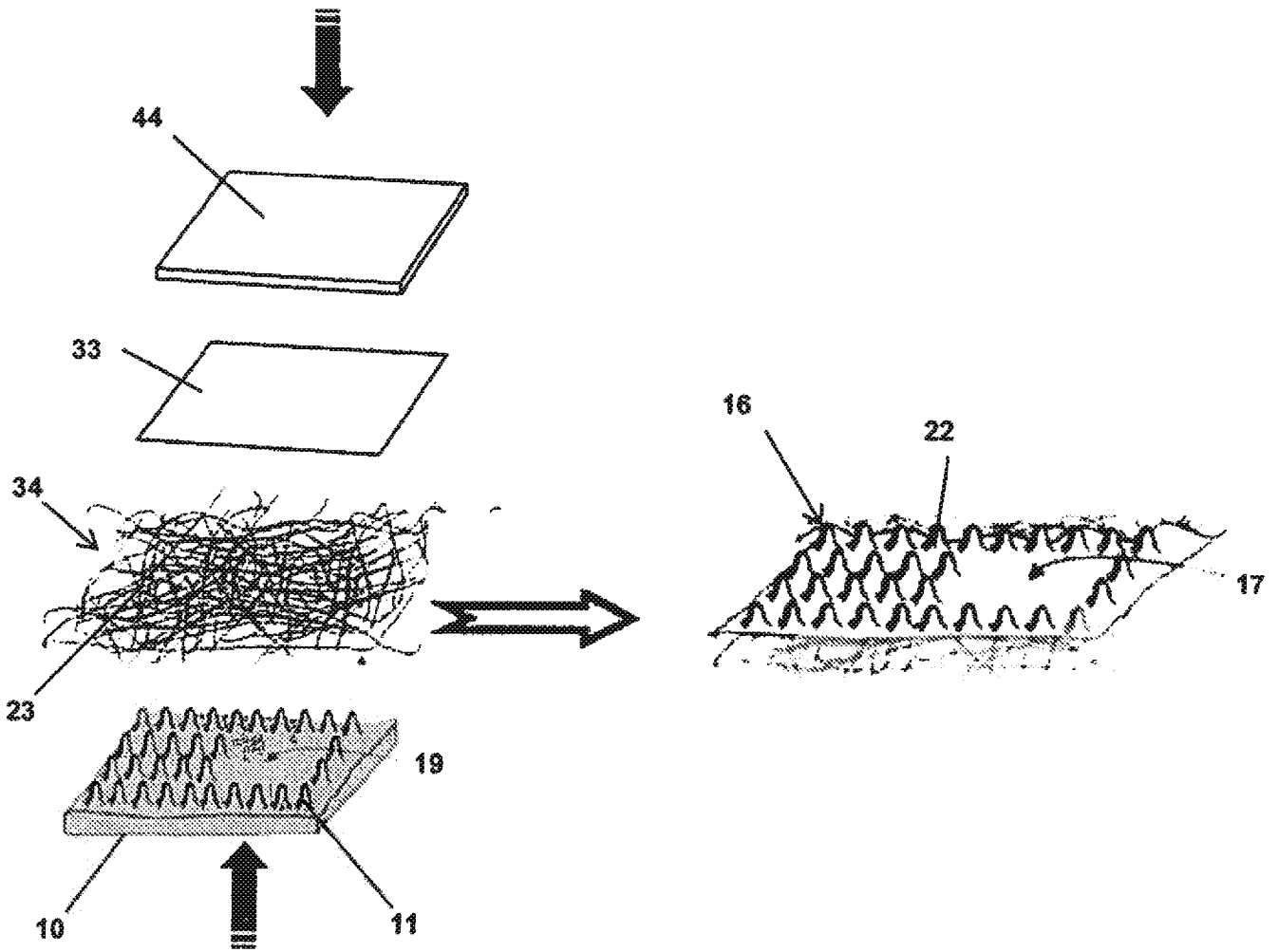
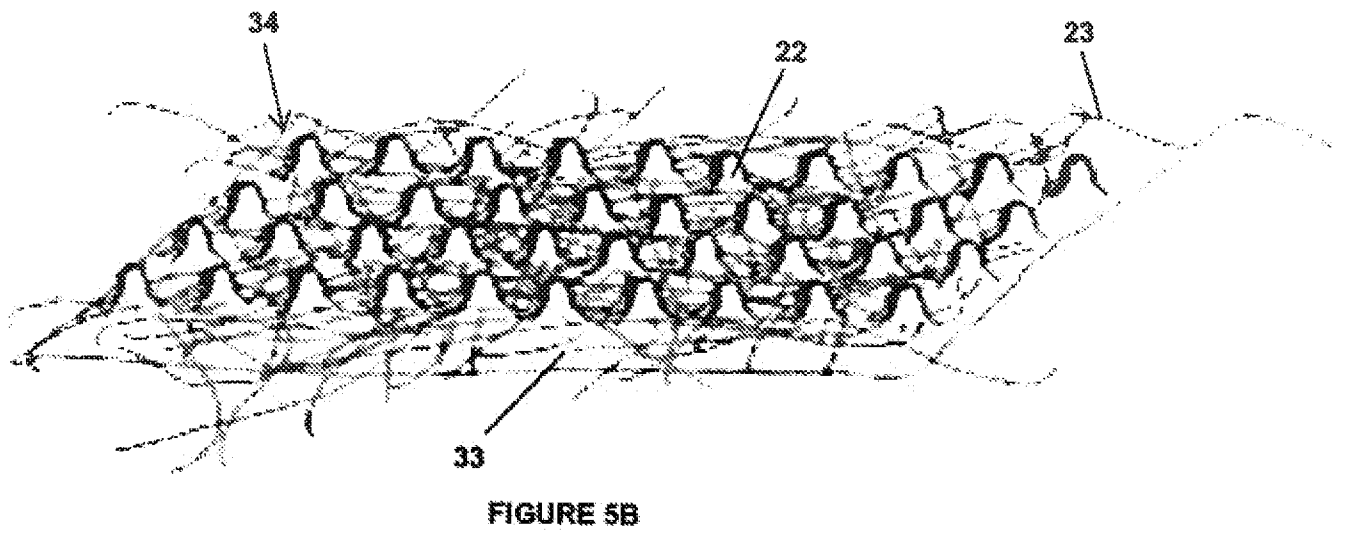
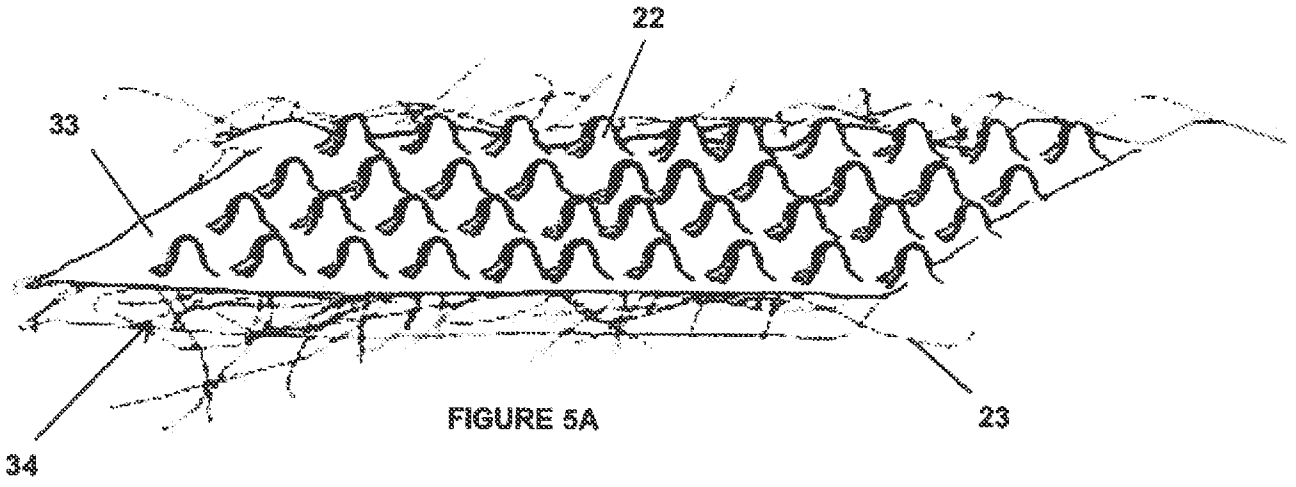


FIGURE 4



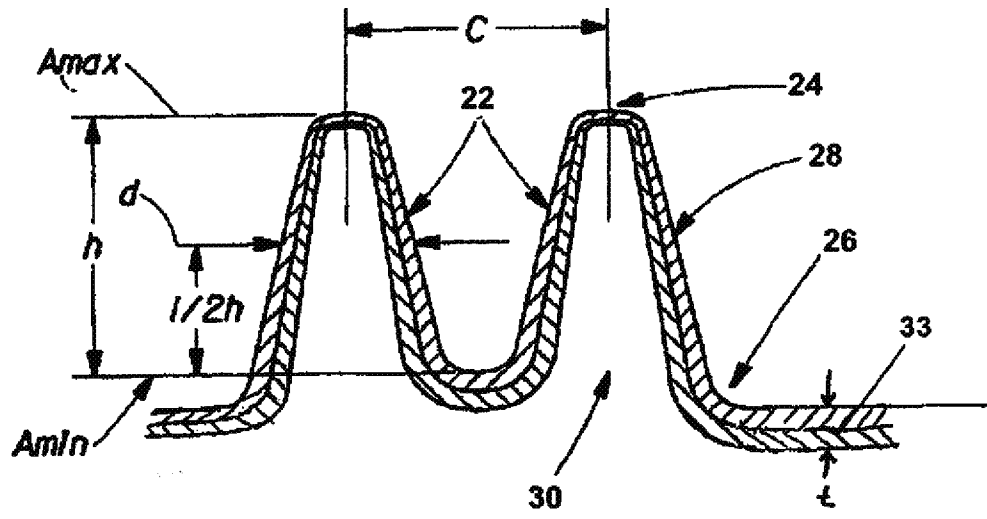


FIGURE 6

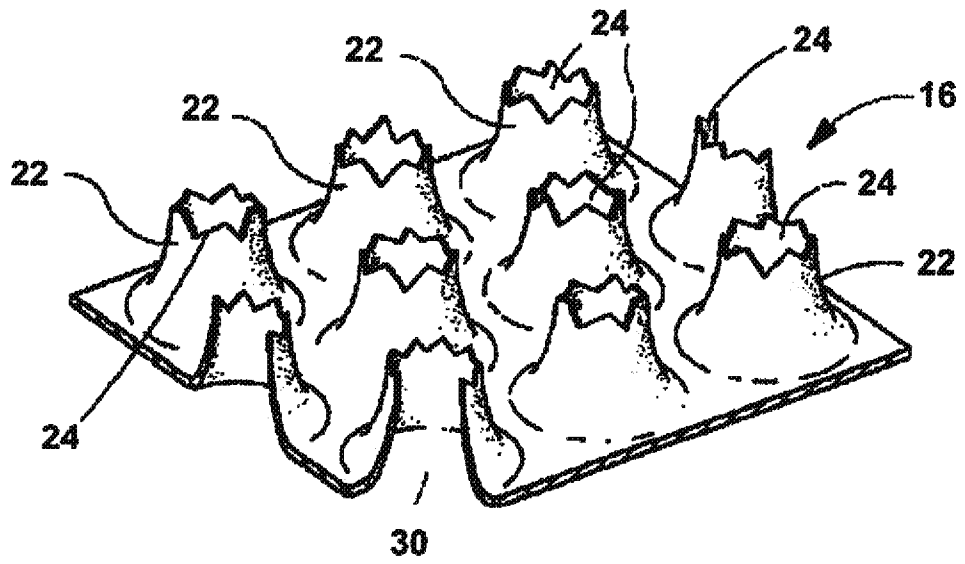


FIGURE 7

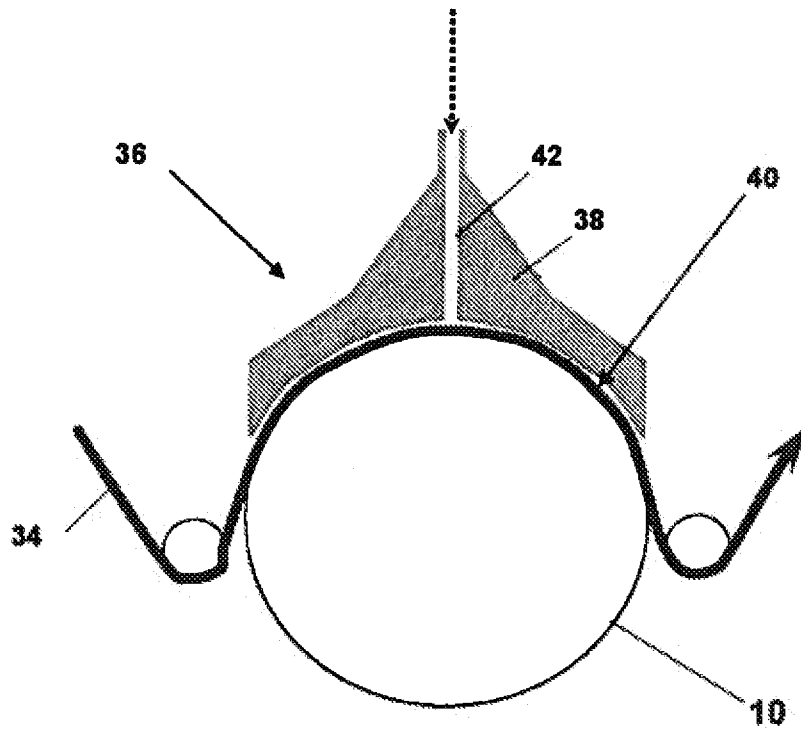


FIGURE 8

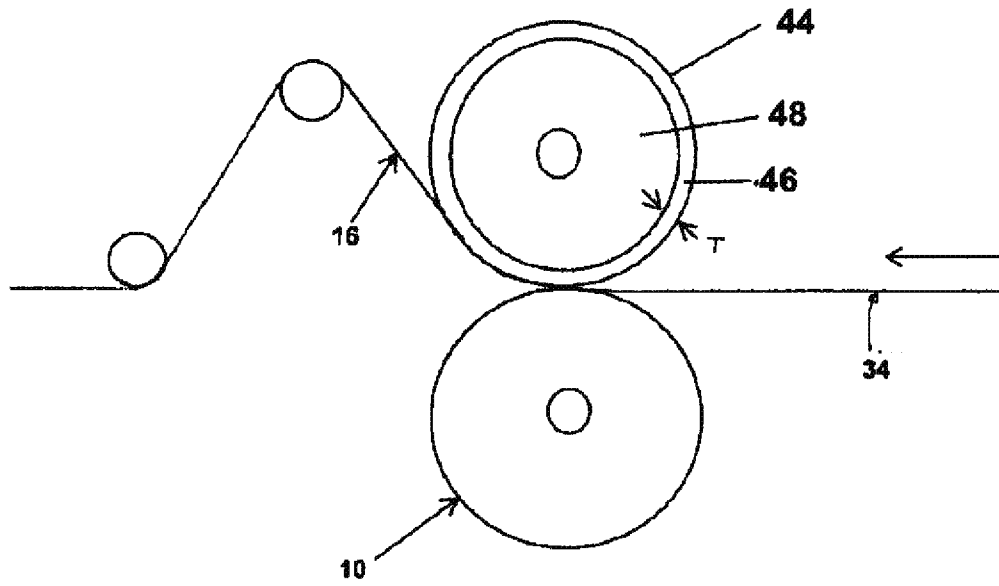


FIGURE 9

INTERNATIONAL SEARCH REPORT

International application No
PCT/US2010/048415

A. CLASSIFICATION OF SUBJECT MATTER
 INV. A61F13/15 B26F1/24 B29C65/00 B32B3/10 B32B27/12
 ADD.
 According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED
 Minimum documentation searched (classification system followed by classification symbols)
 A61F B26F B29C B32B

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practical, search terms used)
 EPO-Internal

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	EP 0 995 414 A1 (PANTEX SRL [IT]) 26 April 2000 (2000-04-26) paragraphs [0019] - [0020], [0037] - [0038]; claim 18; figures 1,3,5	1-20
X	WO 94/24354 A1 (GUIAL SA [FR]; BEZIER BERNARD [FR]) 27 October 1994 (1994-10-27) claims 1,6; figures 1,3	1-20
X	US 2004/209041 A1 (MUTH MATHIAS [DE] ET AL) 21 October 2004 (2004-10-21) column 45; figures 1,2,4a,4b	1-20
X	US 4 995 930 A (MERZ WINFRIED [DE] ET AL) 26 February 1991 (1991-02-26) column 1, line 38 - column 2, line 9; figures 1-3 column 2, line 40 - column 3, line 5	1-20
	-/--	

Further documents are listed in the continuation of Box C.

See patent family annex.

* Special categories of cited documents :

- "A" document defining the general state of the art which is not considered to be of particular relevance
- "E" earlier document but published on or after the international filing date
- "L" document which may throw doubts on priority claim(s) or which is cited to establish the publication date of another citation or other special reason (as specified)
- "O" document referring to an oral disclosure, use, exhibition or other means
- "P" document published prior to the international filing date but later than the priority date claimed

- "T" later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the invention
- "X" document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone
- "Y" document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art.
- "&" document member of the same patent family

Date of the actual completion of the international search

15 November 2010

Date of mailing of the international search report

06/12/2010

Name and mailing address of the ISA/

European Patent Office, P.B. 5818 Patentlaan 2
 NL - 2280 HV Rijswijk
 Tel. (+31-70) 340-2040,
 Fax: (+31-70) 340-3016

Authorized officer

Elsässer, Ralf

INTERNATIONAL SEARCH REPORT

International application No

PCT/US2010/048415

C(Continuation). DOCUMENTS CONSIDERED TO BE RELEVANT		
Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	WO 96/26697 A1 (TREDEGAR IND INC [US]) 6 September 1996 (1996-09-06) claim 1; figures 4a,7 -----	1-20
X	WO 99/30658 A1 (PROCTER & GAMBLE [US]; GRAY BRIAN FRANCIS [JP]) 24 June 1999 (1999-06-24). page 19, line 30 - page 20, line 4; claims 20-27; figures 14,16 -----	1-20
A	WO 01/08869 A1 (POTLATCH CORP [US]) 8 February 2001 (2001-02-08) page 1, lines 17-20 page 2, lines 21-22 page 3, lines 3-4 -----	1-20

INTERNATIONAL SEARCH REPORT

Information on patent family members

International application No

PCT/US2010/048415

Patent document cited in search report	Publication date	Patent family member(s)	Publication date
EP 0995414	A1	26-04-2000	DE 69817829 D1 09-10-2003
			DE 69817829 T2 15-07-2004
			ES 2205431 T3 01-05-2004
WO 9424354	A1	27-10-1994	AT 167711 T 15-07-1998
			AU 6541294 A 08-11-1994
			BR 9405142 A 31-08-1999
			CA 2138253 A1 27-10-1994
			CN 1107279 A 23-08-1995
			DE 69411241 D1 30-07-1998
			DE 69411241 T2 12-11-1998
			DK 646193 T3 26-10-1998
			EP 0646193 A1 05-04-1995
			ES 2119193 T3 01-10-1998
			FR 2704179 A1 28-10-1994
			JP 7508448 T 21-09-1995
			US 2004209041
AT 290943 T 15-04-2005			
AU 2002325864 B2 20-10-2005			
AU 2002328838 B2 01-09-2005			
CN 1525911 A 01-09-2004			
CN 1522190 A 18-08-2004			
WO 03004259 A2 16-01-2003			
WO 03004229 A1 16-01-2003			
EP 1425161 A2 09-06-2004			
EP 1425143 A1 09-06-2004			
ES 2240793 T3 16-10-2005			
JP 4074854 B2 16-04-2008			
JP 2004533339 T 04-11-2004			
JP 3924564 B2 06-06-2007			
JP 2005520702 T 14-07-2005			
JP 4528756 B2 18-08-2010			
JP 2007083394 A 05-04-2007			
JP 2007229923 A 13-09-2007			
JP 2010046794 A 04-03-2010			
KR 20060018930 A 02-03-2006			
MX PA03011788 A 02-04-2004			
MX PA03011953 A 26-03-2004			
PL 365209 A1 27-12-2004			
PT 1425161 E 30-04-2007			
US 2004209067 A1 21-10-2004			
US 2008014408 A1 17-01-2008			
US 4995930	A	26-02-1991	DE 3521374 A1 18-12-1986
			DK 279086 A 15-12-1986
US 4995930	A		EP 0209713 A2 28-01-1987
			ES 8800089 A1 01-01-1988
			GR 861322 A1 19-09-1986
			JP 61293835 A 24-12-1986
			NO 862369 A 15-12-1986
WO 9626697	A1	06-09-1996	US 6242074 B1 05-06-2001
WO 9930658	A1	24-06-1999	AT 270535 T 15-07-2004
			AU 5527898 A 05-07-1999
			CA 2310780 A1 24-06-1999

INTERNATIONAL SEARCH REPORT

Information on patent family members

International application No PCT/US2010/048415

Patent document cited in search report		Publication date	Patent family member(s)	Publication date
			CN 1537520 A	20-10-2004
			DE 69729811 D1	12-08-2004
			DE 69729811 T2	04-08-2005
			EP 1047364 A1	02-11-2000
			JP 3423725 B2	07-07-2003
			JP 2001504766 T	10-04-2001
			ZA 9811399 A	30-08-1999
WO 0108869	A1	08-02-2001	CA 2345611 A1	08-02-2001
			MX PA01003299 A	24-06-2003
			US 6368539 B1	09-04-2002